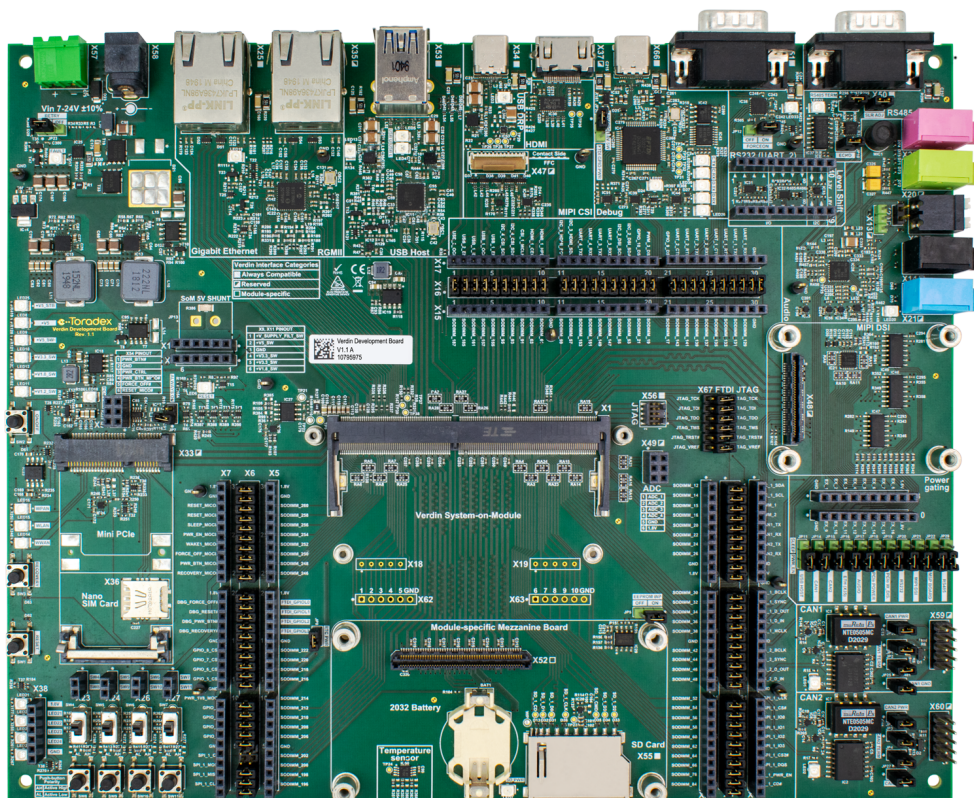


Verdin Development Board

HW Datasheet



Revision History

Document Revisions

Date	Doc. Revision	Product Version	Changes
20-Apr-2021	Rev. 1.00	V1.1	Initial release.
22-Jun-2021	Rev. 1.01	V1.1	Updated the PHY status LED signal names according to the 1.3 version of the Verdin Family Specification throughout the whole document.
25-Aug-2022	Rev. 1.02	V1.1	<p> Section 1.1: Reference documents links have been updated. Section 1.4: Typo has been fixed on the Figure 1. Section 2.4: LED17 color has been changed from "Green" to "Red". Section 2.12.1: Typo has been fixed on the Figure 7. Section 2.18: Temperature sensor has been added. Section 2.19: EEPROM has been added. Section 2.21: Typo has been fixed on the Figure 11. Minor Changes. </p>
26-Oct-2023	Rev. 1.03	V1.1	<p> Section 1: Added note about Verdin DSI to HDMI adapter. Section 1.1.18: Added to document. </p>
01-Mar-2024	Rev. 1.04	V1.1	<p> Section 2.4: Add information about PCAL6416AHF GPIO expander. Section 2.7.1: Corrected Ethernet_1 signal names on Table 17. Section 2.7.2: Corrected Ethernet_2 signal names on Table 18. Section 2.8.1: Corrected USB signal names on Table 21. Section 2.10.1: Corrected SD Card Connector number. Section 2.11.1: Corrected HDMI Connector number. Section 2.13.1.5: Corrected SPEAKER OUT 3-pin header connector number. Section 2.13.1.6: Corrected SPEAKER OUT 2-pin header section name. Section 2.14.1: Corrected MIPI CSI signal name on Table 35. Section 2.15.1.1.2: Corrected CAN description on Table 38. Section 2.21: Corrected FT4232HL Connected/Controlled Net on Table 55. Section 2.21.1.1: Corrected USB Debugger signal name on Table 57. Minor changes </p>

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1 Introduction

The Verdin Development Board is a flexible development board with which you can explore and evaluate the functionality and performance of the Verdin product family.

Complementing the Verdin computer on module, Verdin Development Board supports a wide variety of industry-standard interfaces while at the same time providing advanced multimedia and high-speed connectivity options, making it suitable for an almost unlimited number of applications. Verdin interfaces can be easily accessed using physical connectors and standard pitch headers.

The Verdin Development Board is built on a 4-layer printed circuit board (PCB), and only one layer is used for high-speed signal routing. This demonstrates how Direct Breakout technology makes it incredibly easy to implement leading-edge interfaces with minimal risk and effort. CAE data for the board, including schematics, layout, and IPC-7351 compliant component libraries, are freely downloadable from the Toradex developer website.

To ensure optimal compatibility and user experience with the Verdin Development Board, it must be ordered with the [Verdin DSI to HDMI Adapter](#). This adapter uses a MIPI DSI interface to provide an HDMI output that seamlessly integrates with all Verdin System on Modules, guaranteeing an enhanced and comprehensive user experience.

1.1 Reference Documents

For detailed technical information, please refer to the documents listed below.

1.1.1 Verdin Family Specification

<https://docs.toradex.com/109262-verdin-family-specification.pdf>

1.1.2 Verdin Carrier Board Design Guide

<https://docs.toradex.com/108140-verdin-carrier-board-design-guide.pdf>

1.1.3 Verdin Computer on Module family overview

<https://www.toradex.com/computer-on-modules/Verdin-arm-family>

1.1.4 Toradex Developer Website – Verdin Computer on Module documents

<https://developer.toradex.com/products/verdin-som-family/modules>

1.1.5 Carrier Board Layout Guide

<https://docs.toradex.com/102492-layout-design-guide.pdf>

1.1.6 Toradex Developer Website – Verdin Development Board Design Files

<https://developer.toradex.com/products/verdin-development-board>

1.1.7 Pushbutton On/Off controller datasheet

<https://www.analog.com/media/en/technical-documentation/data-sheets/2954fb.pdf>

1.1.8 EEPROM datasheet

<https://www.st.com/resource/en/datasheet/m24c02-w.pdf>

1.1.9 Temperature sensor datasheet

<https://www.ti.com/lit/ds/symlink/tmp75c.pdf>

1.1.10 USB HUB datasheet

<https://ww1.microchip.com/downloads/en/DeviceDoc/USB5744-Data-Sheet-DS00001855J.pdf>

1.1.11 Gigabit Ethernet Transceiver datasheet

<https://ww1.microchip.com/downloads/en/DeviceDoc/00002841B.pdf>

1.1.12 RS232 Transceiver datasheet

<https://www.ti.com/lit/ds/symlink/trs3122e.pdf>

1.1.13 RS485 Transceiver datasheet

<https://www.ti.com/lit/ds/symlink/sn65hvd01.pdf>

1.1.14 Audio Codec datasheet

https://www.nuvoton.com/export/resource-files/DS_NAU88C22_DataSheet_EN_Rev1.1.pdf

1.1.15 USB Type-C Configuration Channel Logic IC datasheet

<https://www.ti.com/lit/ds/symlink/tusb321ai.pdf>

1.1.16 UV/OV and Reverse Protection Controller datasheet

<https://www.analog.com/media/en/technical-documentation/data-sheets/LTC4368.pdf>

1.1.17 GPIO expander datasheet

<https://www.nxp.com/docs/en/data-sheet/PCAL6416A.pdf>

1.1.18 Toradex Developer Website – Verdin DSI to HDMI Adapter

<https://developer.toradex.com/hardware/verdin-som-family/add-ons/verdin-dsi-to-hdmi-adapter/>

1.2 Abbreviations

Table 1: Abbreviations

Abbreviation	Explanation
ADC	Analog to Digital Converter
CAN	Controller Area Network, a bus that is mainly used in the automotive and industrial environment
CAN FD	Controller Area Network Flexible Data-Rate, an extension to the original CAN bus protocol which allows higher data rates and larger message sizes.
CEC	Consumer Electronic Control, HDMI feature that allows controlling CEC compatible devices
CPU	Central Processor Unit
CSI	Camera Serial Interface
DAC	Digital to Analog Converter
DDC	Display Data Channel, interface for reading out the capability of a monitor. In this document DDC2B (based on I2C) is always meant.
DFP	Downstream Facing Port, USB Type-C port that acts as a host
DRP	Dual-Role Port, USB Type-C port that can operate as power sink and source
DSI	Display Serial Interface
DVI	Digital Visual Interface, digital signals are electrically compatible with HDMI
EDID	Extended Display Identification Data, timing setting information provided by the display in a PROM
EMI	Electromagnetic Interference, high-frequency disturbances
ESD	Electrostatic Discharge, high voltage spike or spark that can damage electrostatic-sensitive devices
FPD-Link	Flat Panel Display Link, high-speed serial interface for liquid crystal displays. In this document is also called the LVDS interface.
GBE	Gigabit Ethernet, Ethernet interface with a maximum data rate of 1000Mbit/s
GND	Ground
GND_CHASSIS	Chassis Ground
GPIO	General Purpose Input/Output, pin that can be configured as an input or output
GSM	Global System for Mobile Communications
HDA	High-Definition Audio (HD Audio), the digital audio interface between CPU and audio codec
I2C	Inter-Integrated Circuit, the two-wire interface for connecting low-speed peripherals
I2S	Integrated Interchip Sound, serial bus for connecting PCM audio data between two devices
I/O	Input-Output
JTAG	Joint Test Action Group, widely used debug interface
LCD	Liquid Crystal Display
LSB	Least Significant Bit
LVDS	Low-Voltage Differential Signaling, electrical interface standard that can transport high-speed signals over twisted-pair cables. Many interfaces like PCIe or SATA use this interface. Since the first successful application was the Flat Panel Display Link, LVDS became a synonymous for this interface. In this document, the term LVDS is used for the FPD-Link interface.
MAC	Medium Access Control is part of the second layer (data link layer) in the Ethernet stack
MIPI	Mobile Industry Processor Interface Alliance
MDI	Medium Dependent Interface, the physical interface between Ethernet PHY and cable connector
MDIO	Management Data Input/Output, an interface that is used for controlling the Ethernet PHY. The bus consists of the MDC clock and the MDIO bidirectional data signal.
mini PCIe	PCI Express Mini Card, the card form factor for internal peripherals. The interface features PCIe and USB 2.0 connectivity
MMC	MultiMediaCard, flash memory card

Continued on next page

Table 1: Abbreviations (Continued)

Abbreviation	Explanation
MSB	Most Significant Bit
NC	Not Connected
OD	Open-Drain
OTG	USB On-The-Go, a USB host interface that can also act as USB client when connected to another host interface
PCB	Printed Circuit Board
PCI	Peripheral Component Interconnect, parallel computer expansion bus for connecting peripherals
PCIe	PCI Express, a high-speed serial computer expansion bus, replaces the PCI bus
PCM	Pulse-Code Modulation, digitally representation of analog signals, standard interface for digital audio
PD	Pull-Down Resistor
PHY	The physical layer of the OSI model
PU	Pull-up Resistor
PWM	Pulse-Width Modulation
PWR	Power
QSPI	Quad SPI, SPI interface with four bidirectional data signals
RGMII	Reduced Gigabit Media-Independent Interface, the interface between Ethernet MAC and PHY for up to 1Gb/s
RJ45	Registered Jack, common name for the 8P8C modular connector that is used for Ethernet wiring
RS232	The single-ended serial port interface
RS485	Differential signaling serial port interface, half-duplex, multi-drop configuration possible
R-UIM	Removable User Identity Module, identifications card for CDMA phones and networks, an extension of the GSM SIM card
SD	Secure Digital, flash memory card
SDIO	Secure Digital Input Output, an external bus for peripherals that uses the SD interface
SIM	Subscriber Identification Module, an identification card for GSM phones
SMBus	System Management Bus (SMB), a two-wire bus based on the I ² C specifications, is used in x86 designs for system management.
SoC	System on a Chip, IC which integrates the main component of a computer on a single chip
SoM	System on a Module, PCB which integrates the main component of a computer on a single board
SPI	Serial Peripheral Interface Bus, synchronous four-wire full-duplex bus for peripherals
TIM	Thermal Interface Material, thermally conductive material between CPU and heat spreader or heat sink
TMDS	Transition-Minimized Differential Signaling, serial high-speed transmitting technology that is used by DVI and HDMI
TVS Diode	Transient-Voltage-Suppression Diode, a diode that is used to protect interfaces against voltage spikes
UFP	Upstream Facing Port, USB Type-C port that acts as a client
UART	Universal Asynchronous Receiver/Transmitter, serial interface, in combination with a transceiver an RS232, RS422, RS485, IrDA or similar interface can be achieved
USB	Universal Serial Bus, serial interface for internal and external peripherals

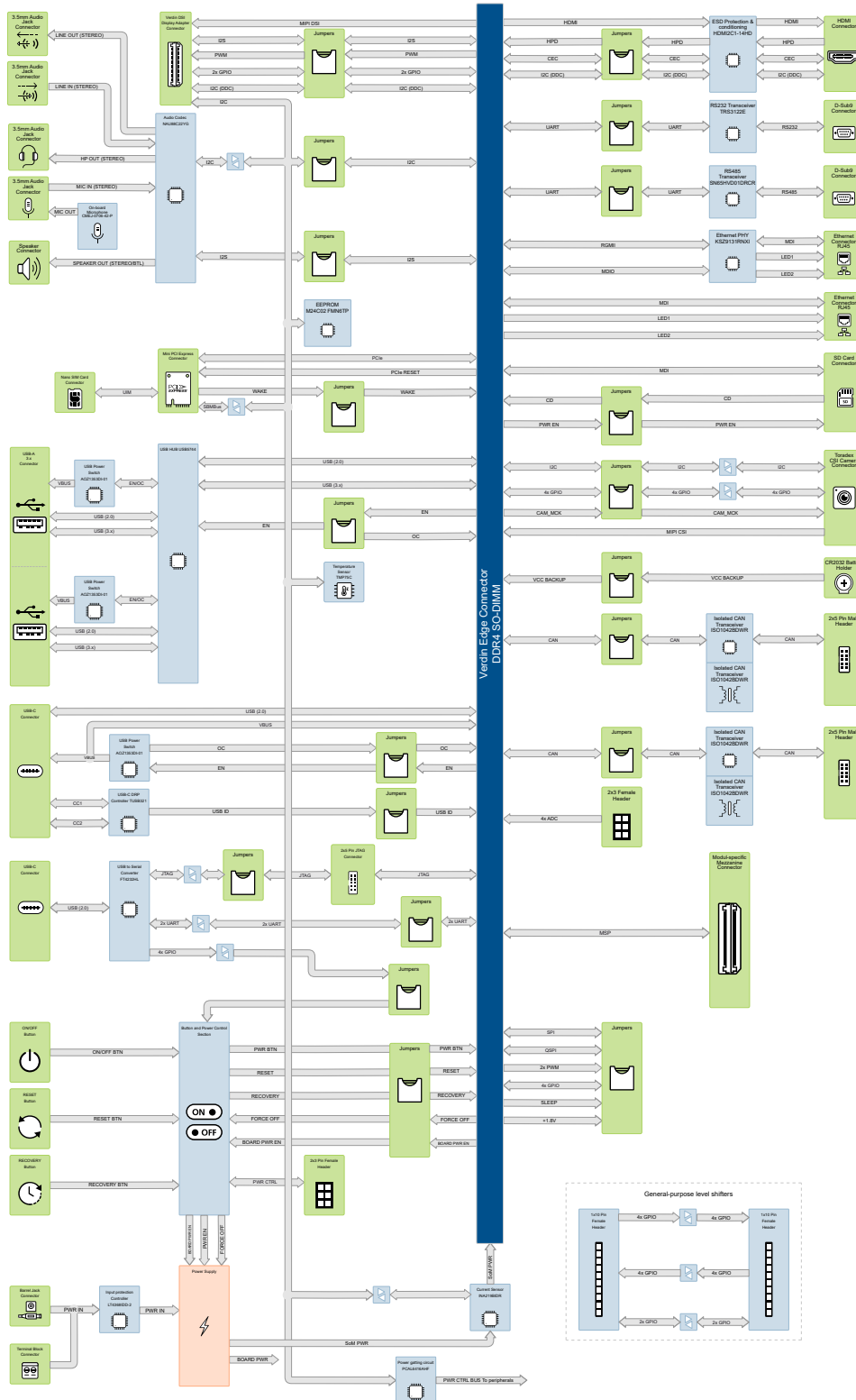
1.3 Main Features

The Verdin Development Board provides the following features and communication interfaces:

- 1x stacked USB 3.0 Type-A connector, featuring 2x USB ports through the on-board USB HUB
- 1x USB-C connector providing USB Dual-Role-Port (DRP) or host/client functionality
- 1x USB-C debug connector (optionally connected to UART3, UART4, and JTAG through the multi-purpose USB to serial converter based on the FT4232HL IC)
- 2x RJ45 connectors featuring 10/100/1000 Mbps Ethernet interfaces (1x Ethernet transceiver placed on the Development Board)
- 1x Mini PCIe Connector
- 1x HDMI Type A connector
- 1x *"Module-specific"* Board Connector
- 1x MIPI[®] CSI Camera Interface connector
- 1x MIPI DSI Display interface with a board-to-board connector which allows for connecting various DSI display adapters: DSI to HDMI, DSI to LVDS, DSI to parallel RGB, etc.
- 1x JTAG connector
- 1x 4-bit SD[®] Card connector
- 1x I²C 2Kb EEPROM IC
- 1x Digital Temperature Sensor
- Audio I/O on 3.5mm stereo jacks (MIC IN, AUX IN, HEADPHONE OUT, AUX OUT), terminal block/pin header connectors (SPEAKER OUT), and on-board electret microphone
- 1x RS232 Serial Interface on a 9-pin D-Sub Connector
- 1x RS485 Serial Interface on a 9-pin D-Sub Connector
- 4x I²C, 1x SPI and 3x PWM interfaces
- 4x ADC inputs
- 2x CAN interface headers, both supporting regular CAN (up to 1Mbps) and CAN FD (up to 5Mbps)
- 1x Real-time clock backup battery holder
- 4x dedicated GPIOs
- 4x general-purpose LEDs, switches and pushbuttons
- 10x level-shifted GPIOs (1.8V to 3.3V and vice versa)
- Power gating circuit (allows Power ON and OFF control of various development board peripherals)
- Extremely flexible and easy to use low-speed signal breakout and jumper area allowing easy signal re-routing, external connection, and measurement/probing
- Undervoltage, overvoltage, overcurrent and reverse voltage protected power input

1.4 Hardware Architecture Block Diagram

Figure 1: Verdin Development Board Hardware Architecture



1.5 Physical Drawing

1.5.1 Top Side Connectors

Figure 2: Verdin Development Board connectors and controls

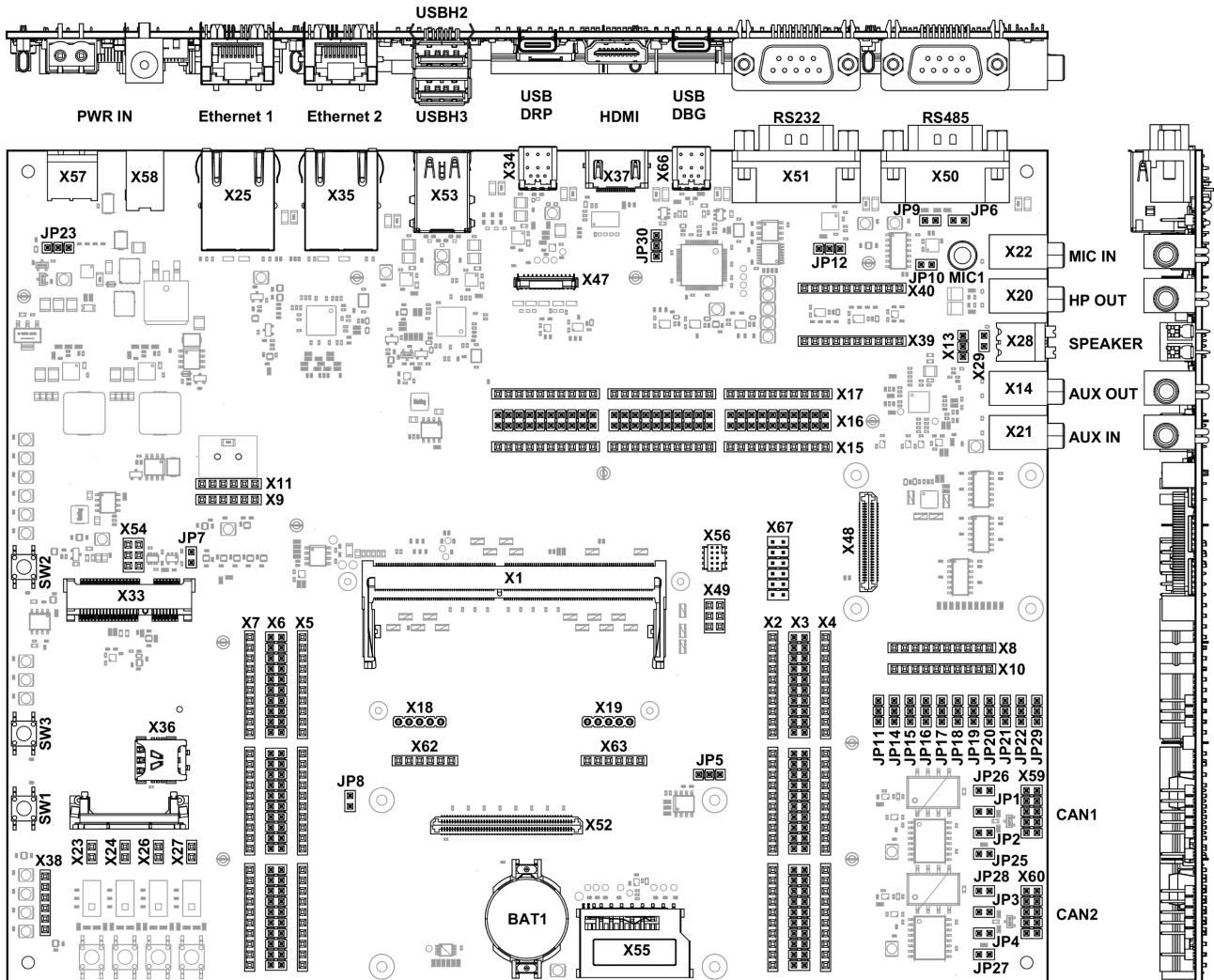


Table 2: Top Side Connectors

Designator	Description	Remarks
X1	Verdin module edge connector (DDR4 SO-DIMM)	
X2	Verdin edge connector breakout section 1	
X3	Verdin edge connector breakout section 1	
X4	Verdin edge connector breakout section 1	
X5	Verdin edge connector breakout section 2	
X6	Verdin edge connector breakout section 2	
X7	Verdin edge connector breakout section 2	
X8	I ² C GPIO Expander I/Os header	
X9	Power out header	
X10	I ² C GPIO Expander I/Os header	
X11	Power out header	
X13	Analog audio SPEAKER OUT 3-pin header	Stereo
X14	Analog audio AUX OUT jack	Auxiliary out / Line out (Stereo)
X15	Verdin edge connector breakout section 3	
X16	Verdin edge connector breakout section 3	
X17	Verdin edge connector breakout section 3	
X18	POGO pins	
X19	POGO pins	
X20	Analog audio HEADPHONE OUT jack	Stereo
X21	Analog audio AUX IN jack	Auxiliary in / Line in (Stereo)Stereo
X22	Analog audio MIC IN jack	Stereo
X23	User button and switch header	
X24	User button and switch header	
X25	Ethernet connector	Ethernet_1
X26	User button and switch header	
X27	User button and switch header	
X28	Analog audio SPEAKER OUT connector	Mono (screwless connector)
X29	Analog audio SPEAKER OUT 2-pin header	Mono
X33	Mini PCIe connector	
X34	USB DRP connector	USB-C (USB 2.0 only)
X35	Ethernet connector	Ethernet_2
X36	SIM Card Holder	Nano SIM
X37	HDMI connector	
X38	User LEDs header	
X39	Level shifter header	3.3V
X40	Level shifter header	1.8V
X47	MIPI CSI Camera connector	
X48	MIPI DSI Display Adapter connector	

Continued on next page

Table 2: Top Side Connectors (Continued)

Designator	Description	Remarks
X49	ADC input header	
X50	RS485 connector	9-pin D-Sub
X51	RS232 connector	9-pin D-Sub
X52	<i>"Module-specific" Mezzanine Board connector</i>	
X53	2x USB3.x HOST connector	UPPER: USBH3 - LOWER: USBH2
X54	Power control header	
X55	SD Card 4-bit connector	
X56	JTAG connector	
X57	Terminal Block Power Supply connector	7-24V \pm 10%
X58	Barrel Jack Power Supply connector	7-24V \pm 10%
X59	CAN1 interface header	Isolated
X60	CAN2 interface header	Isolated
X62	POGO pin header	
X63	POGO pin header	
X66	USB to Serial, USB to JTAG interface connector	USB-C connector (USB 2.0 only)
X67	USB Debugger to JTAG interface jumper array	

2 Interface Description

2.1 Verdin System-On-Module

Connector Type: 260 pin DDR4 SO-DIMM socket

Manufacturer: TE 2309409-2

For the pinout of the Verdin module, please refer to the applicable Verdin module datasheet or to the Verdin Family Specification / Verdin Carrier Board Design guide for the abstract pinout. Stand-offs are available on Verdin Development Board for affixing the Verdin module to the Development Board. It is recommended to use M2×0.4 size screws to fasten the Verdin module with the stand-offs.

2.2 Power Supply

The Verdin Development Board has two different power connectors that can power the board: X57, X58 is both wide input range connectors tied together.



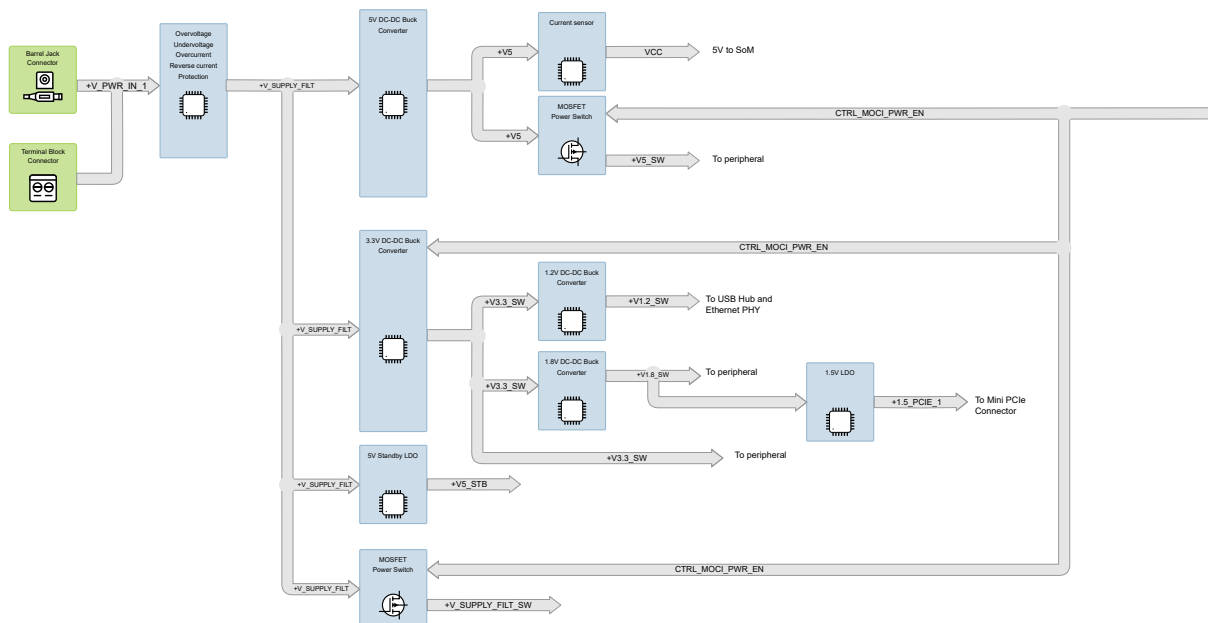
The Barrel Jack Power Connector X58 and the Terminal Block Power Connector X57 are electrically connected, and only one of these connectors should be used for powering the board. The simultaneous connection of two power supplies is not allowed. Violating this requirement may cause power supplies or Development Board damage.



Input voltage can vary across a range of 7-24V ±10%. The maximum input current is limited to 5A. If your application dissipates more than 35W, please work with a higher input voltage, up to 24V.

Several power domains are available on the Development Board. The board's power supply architecture is shown in the picture below.

Figure 3: Power supply architecture



The on-board power supplies provide the following nominal voltages and currents.

Table 3: On-Board Power Supplies

Nominal voltage	Maximum current	Maximum power
5V	8A	40W
3.3V	8A	26.4W
1.8V	2A	3.6W

2.2.1 Terminal Block Power Supply Connector (X57)

Connector Type: AUK TB5102PRB-H

Table 4: Terminal Block Power Supply Connector (X57)

Pin	Description	Voltage / Range
1	GND	
2	+V_PWR_IN_1	7-24V \pm 10%

2.2.2 Barrel Jack Power Supply Connector (X58)

Connector Type: SWC RAPC722X

Table 5: Barrel Jack Power Supply Connector (X58)

Pin	Description	Voltage / Range
1	+V_PWR_IN_1	7-24V \pm 10%
2	GND	

2.2.3 Power Out Header (X9, X11)

Two female pin headers X9, X11, with main system voltages are available on it, can be used for powering external boards and modules. Pinout of the X9, X11 connectors is identical.

Connector Type: 1×6 Pin Header Female, 2.54mm pitch

Table 6: Power Out Header (X9, X11)

Pin	Description	Remarks
1	+V_SUPPLY_FILT_SW	
2	+V_5_SW	
3	GND	
4	+V3.3_SW	
5	+V3.3_SW	
6	+V1.8_SW	

2.2.4 Power Control

The Verdin Development Board power control is implemented using the Linear LTC2954 Pushbutton On/Off controller and with the signal CTRL_PWR_EN_MOCI, used to enable the peripheral power supplies. For further information about the signals provided by the LTC2954 controller, please refer to its [datasheet](#). For more information regarding the power-up sequence implemented on the board, please refer to the document [Verdin Carrier Board Design Guide](#). The switches SW1 and SW2 have been assigned to the RESET and ON/OFF functions, respectively. The SW3 is used to put the installed Verdin Computer Module into RECOVERY mode. Board power also can be controlled by the Verdin Computer Module with an open drain (OD) CTRL_FORCE_OFF_MOCI# signal. This feature allows the Verdin module to perform a proper power-down procedure. For more details, please refer to the “Verdin Carrier Board Design Guide”. The Power CTRL connector X54 allows the Reset and Power Button control signals to be accessed externally.

2.2.4.1 Power Control Header (X54)

Connector Type: 2×3 Pin Header Female, 2.54mm pitch

Table 7: Power Control Header (X54)

Pin	Signal Name	IO Type	Voltage	Pull-up/Pull-down	Description
1	PWR_BTN#	I/O (OD)	+1.9V	100k to +1.9V	It is connected to the POWER ON/OFF button SW2. Pulled-up to 1.9V inside pushbutton controller IC. Short pulling down turning on Development Board power and Computer Module. Long pulling down forcing Development Board power off.
2	GND	PWR			
3	PWR_CTRL	I	+3.3V max	100k to GND	Behaviour is similar to the “Always ON” Jumper JP7. HIGH level on the PWR_CTRL input forcing on the Verdin Development Board power.
4	CTRL_PWR_BTN_MICO#	I/O (OD)	+1.8V	on SoM	Pulling down for a longer period of time is shutting down the module. Short pulling down is turning on module from off state. Open-drain input with 100k pull-up resistor to the 1.8V RTC rail is on the module. The signal can be left floating on carrier boards.
5	CTRL_FORCE_OFF_MOCI#	I/O (OD)	+5V	100k to +V5_STB	Forcing the turning-off of the main power rail. This signal is ignored for the first 512ms during the power-up sequence. The signal is 5V tolerant.
6	CTRL_RESET_MICO#	I/O (OD)	+1.8V	on SoM	Open-drain input, which resets the module if shorted to ground. There is an on-module pull-up. This means it can be left floating on the carrier board.

Pin 3 of the X54 connector can be used to override the Pushbutton controller. The following table shows the behavior of the board according to the level of the PWR_CTRL signal:

Table 8: Power Control Behavior

PWR_CTRL	Description
0V	The Pushbutton controller is working normally
3.3V	The Verdin Development Board is Always On when power is applied

2.2.4.2 Always-ON Jumper (JP7)

Jumper JP7 can be used to configure the “Always On” behaviour.

Connector Type: 1×2 Pin Header Male, 2.54 mm pitch

Table 9: Always-ON Jumper (JP7)

Jumper Position	Description
OPEN	The board power supply is controlled with Power On/Off buttons.
CLOSED	The board power supply will be in the "Always On" state. Verdin Development Board will be powered up as soon as external power is applied to the connector X57 or X58.

By default, jumper JP7 is open.

2.2.5 Power Supply Input Protection

Supply input is protected against ESD strikes, reverse voltage polarity, overvoltage, undervoltage, and short circuits. The protection circuit is based on an LTC4368 IC from Analog Devices. For detailed information, please refer to the [LTC4368 datasheet](#).

Table 10: Power Supply Input Ratings

Parameter Name	Min	Typ	Max	Unit
Input voltage (Absolute maximum, limited with an ESD diode)			±30	V
Undervoltage threshold	4.82	4.99	5.17	V
Overvoltage threshold	26.11	27.08	28.09	V
Overcurrent protection	3.96	5	6.06	A
Reverse current protection	99	300	505	mA
Recommended input voltage	6.3	7-24	26.4	V

Jumper JP23 can be used to turn ON or OFF the retry function of the power supply input protection circuit.

Connector Type: 1×3 Pin Header Male, 2.54 mm pitch

Table 11: Jumper Position (JP23)

Jumper Position	Description
1-2	Power supply input will restart automatically after a forward overcurrent fault. The restart delay time is defined by capacitor C300 $5.5ms/nF$. The typical value for the Verdin Development Board is 550ms.
2-3	Power supply input stays OFF after a forward overcurrent fault. The external power supply should be switched OFF and ON to restore the board power.

By default, jumper JP23 is in position 1-2.

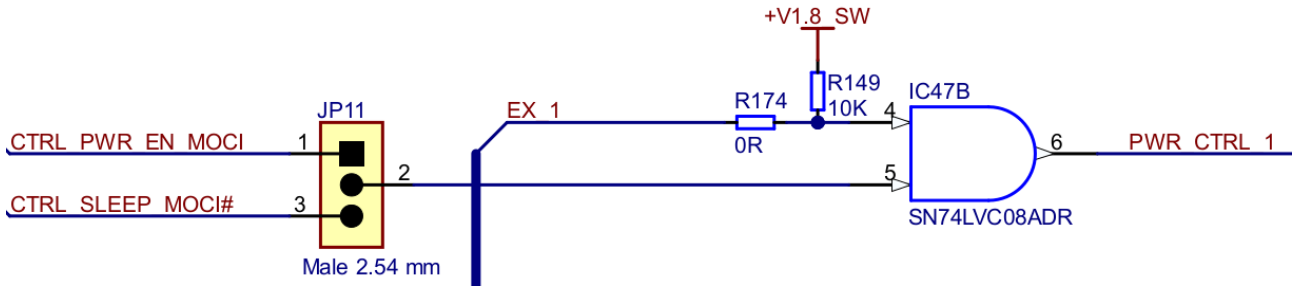
A current, voltage and power measurement IC INA219 (IC27) is also available on Verdin Development Boards. This IC provides an option to measure the power consumption of Verdin modules. IC27 is accessible on the I²C₁ bus at address 0×40.

2.3 Power Gating Circuit

The Verdin development board contains a power gating circuit. This circuit allows for switching ON and OFF separate peripheral modules and provides LEDs to show the respective peripheral module's power state.

There are 3 sources of power gating signals: CTRL_PWR_EN_MOCI, CTRL_SLEEP_MOCI#, EX_1 – EX_11 (from I²C GPIO expander). Please note that when EX_1 – EX_11 signals are High, then the respective peripheral is powered up. PWR_CTRL_1 – PWR_CTRL_11 signals which are going directly to peripherals are not inverted! The source of the power gating signal for each peripheral can be selected via jumpers.

Figure 4: Part of the power gating schematic



The jumpers JP11, JP14, JP15, JP16, JP17, JP18, JP19, JP20, JP21, JP22, JP29 serve the purpose of selecting the power gating source signals.

Connector Type: 1×3 Pin Header Male, 2.54 mm pitch

Table 12: Power Gating Source Signals

Designator	Jumper Position	Power Gating Signal	GPIO Expander Signal	Usage on Carrier	Power Gated Peripheral
JP11	1-2	CTRL_PWR_EN_MOCI	EX1	PWR_CTRL_1	USB HUB
	2-3	CTRL_SLEEP_MOCI#			
JP14	1-2	CTRL_PWR_EN_MOCI	EX2	PWR_CTRL_2	CAN1 transceiver
	2-3	CTRL_SLEEP_MOCI#			
JP15	1-2	CTRL_PWR_EN_MOCI	EX3	PWR_CTRL_3	CAN2 transceiver
	2-3	CTRL_SLEEP_MOCI#			
JP16	1-2	CTRL_PWR_EN_MOCI	EX4	PWR_CTRL_4	Ethernet_2 transceiver
	2-3	CTRL_SLEEP_MOCI#			
JP17	1-2	CTRL_PWR_EN_MOCI	EX5	PWR_CTRL_5	Audio codec
	2-3	CTRL_SLEEP_MOCI#			
JP18	1-2	CTRL_PWR_EN_MOCI	EX6	PWR_CTRL_6	PCIe Power
	2-3	CTRL_SLEEP_MOCI#			
JP19	1-2	CTRL_PWR_EN_MOCI	EX7	PWR_CTRL_7	PCIe Wireless enable
	2-3	CTRL_SLEEP_MOCI#			
JP20	1-2	CTRL_PWR_EN_MOCI	EX8	PWR_CTRL_8	RS232 transceiver
	2-3	CTRL_SLEEP_MOCI#			
JP21	1-2	CTRL_PWR_EN_MOCI	EX9	DSI_PWR_EN	MIPI DSI display adapter
	2-3	CTRL_SLEEP_MOCI#			
JP22	1-2	CTRL_PWR_EN_MOCI	EX10	PWR_CTRL_11	"Module-specific" Mezzanine Board connector
	2-3	CTRL_SLEEP_MOCI#			

Continued on next page

Table 12: Power Gating Source Signals (Continued)

Designator	Jumper Position	Power Gating Signal	GPIO Expander Signal	Usage on Carrier	Power Gated Peripheral
JP29	1-2	CTRL_PWR_EN_MOCI	EX11	PWR_CTRL_12	RS485 transceiver
	2-3	CTRL_SLEEP_MOCI#			

By default, the jumpers JP11, JP14, JP15, JP16, JP17, JP18, JP19, JP20, JP21, JP22, JP29 are installed in positions 1-2.

2.4 GPIO Expander

A PCAL6416AHF GPIO expander IC is used on the board. It is connected to the Verdin I²C signals through pins 12 and 14 of the X1 connector. For more details, please refer to the carrier board [Schematics](#) and the [PCAL6416AHF datasheet](#). EX_1 – EX_16 signals from the GPIO expander are available on headers X8, X10.

2.4.1 GPIO Expander Header (X8)

Connector Type: 1×10 Pin Header Female, 2.54 mm pitch

Table 13: GPIO expander header (X8)

Pin	Signal Name	I/O Type	Voltage	Pull-up/Pull-down
1	GND	PWR		
2	EX_1	O	+1.8V	10k to +V1.8_SW
3	EX_2	O	+1.8V	10k to +V1.8_SW
4	EX_3	O	+1.8V	10k to +V1.8_SW
5	EX_4	O	+1.8V	10k to +V1.8_SW
6	EX_5	O	+1.8V	10k to +V1.8_SW
7	EX_6	O	+1.8V	10k to +V1.8_SW
8	EX_7	O	+1.8V	10k to +V1.8_SW
9	EX_8	O	+1.8V	10k to +V1.8_SW
10	+V1.8_SW	PWR	+1.8V	

2.4.2 GPIO Expander Header (X10)

Connector Type: 1×10 Pin Header Female, 2.54 mm pitch

Table 14: GPIO expander header (X10)

Pin	Signal Name	I/O Type	Voltage	Pull-up/Pull-down
1	GND	PWR		
2	EX_9	O	+1.8V	10k to +V1.8_SW
3	EX_10	O	+1.8V	10k to +V1.8_SW
4	EX_11	O	+1.8V	10k to +V1.8_SW
5	EX_12	O	+1.8V	

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Table 14: GPIO expander header (X10) (Continued)

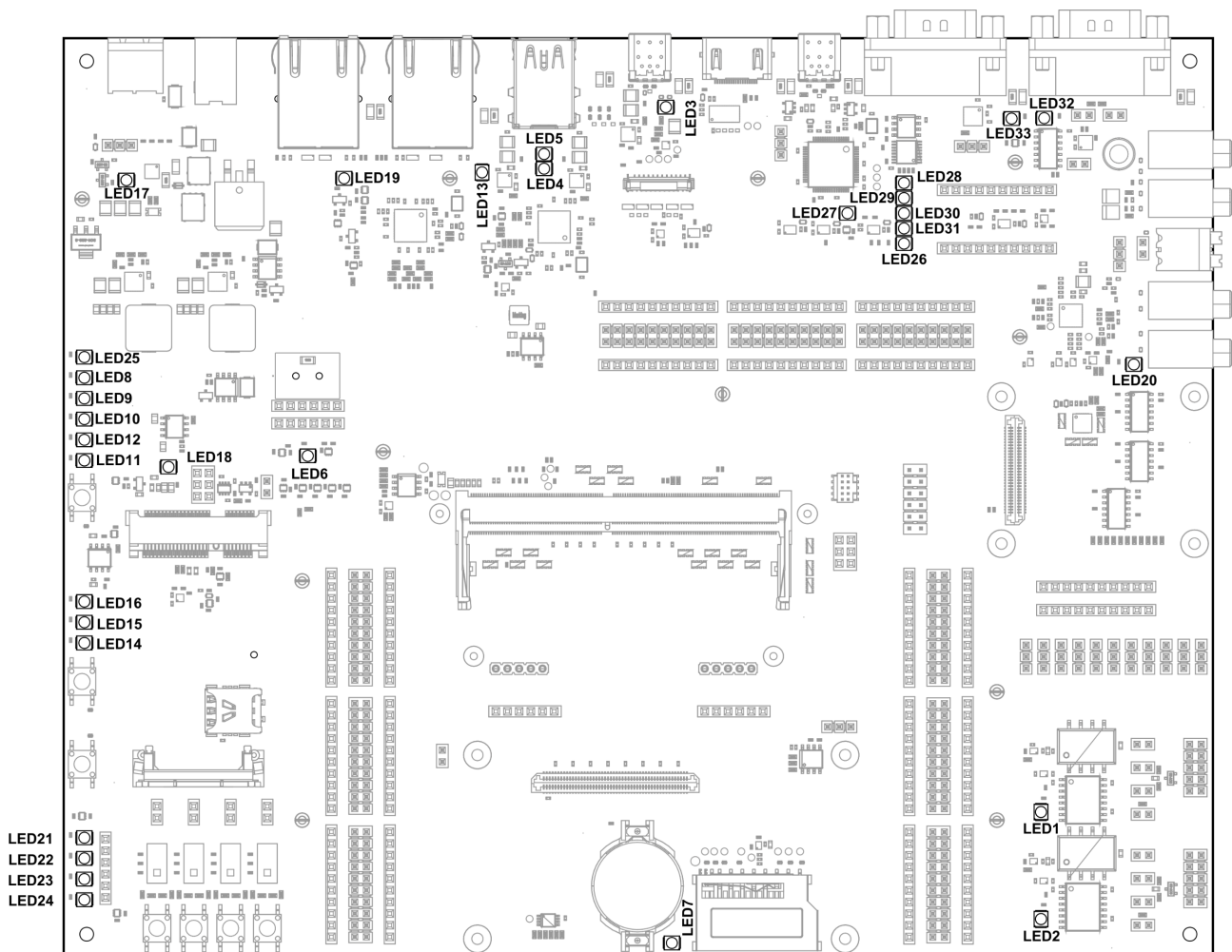
Pin	Signal Name	I/O Type	Voltage	Pull-up/Pull-down
6	EX_13	O	+1.8V	
7	EX_14	O	+1.8V	
8	EX_15	O	+1.8V	
9	EX_16	O	+1.8V	
10	+V1.8_SW	PWR	+1.8V	

EX_12-EX_16 signals are not connected to any peripheral on the Verdin Development Board and can be used as needed.

2.5 Indicator LEDs

The Verdin Development Board features 33 LEDs. These LEDs indicate the statuses of the main power supplies, all power gated peripherals. LEDs are also used for indicating the activity of some peripherals.

Figure 5: Indicator LEDs



The LEDs and their functions are listed in the table below.

Table 15: LEDs Functions

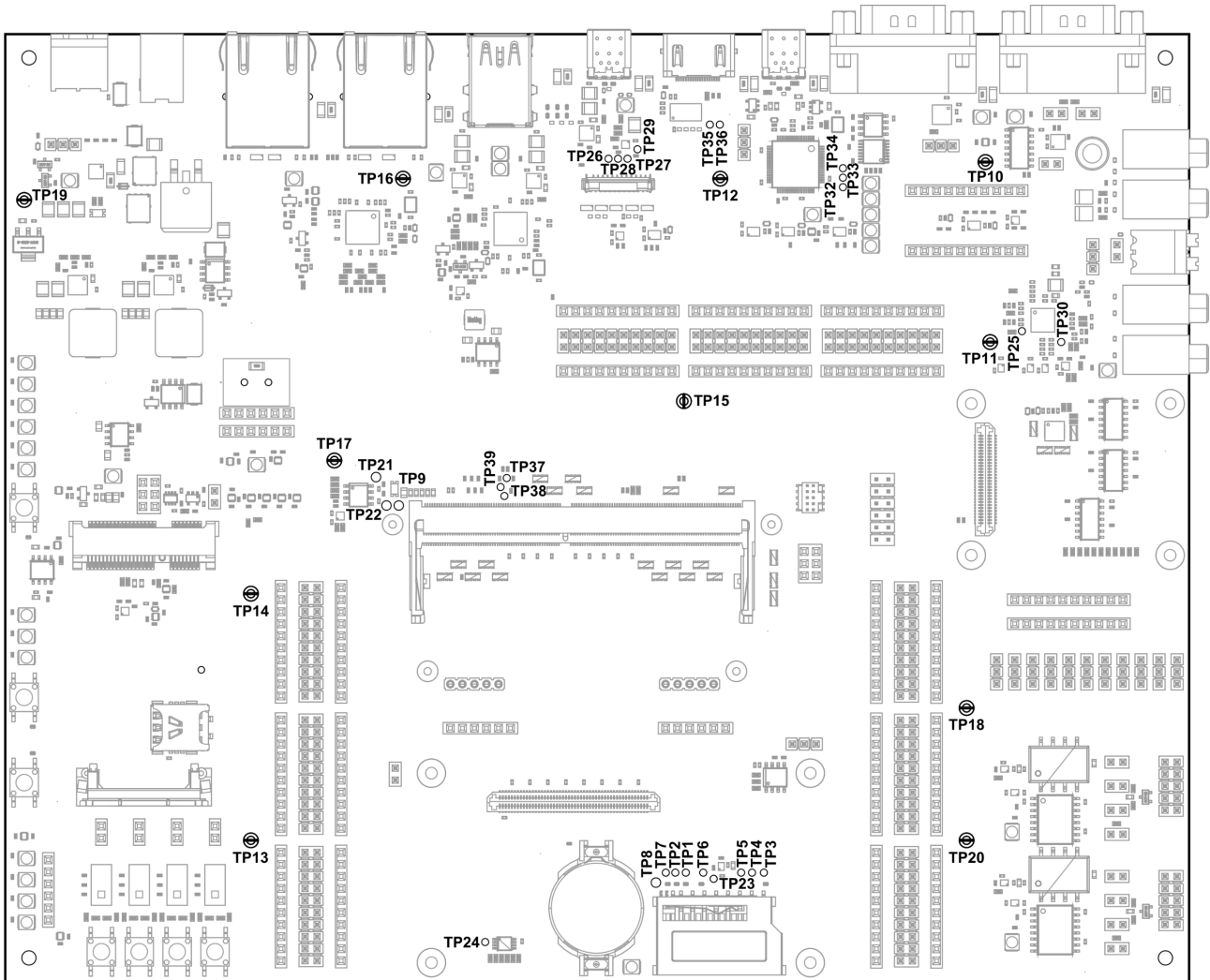
Designator	Color	Description
LED1	Green	LED is lit when CAN_1 transceiver power is ON
LED2	Green	LED is lit when CAN_2 transceiver power is ON
LED3	Green	LED is lit when USB_1 port power is ON (Connector X34)
LED4	Green	LED is lit when USBH3 Host power is ON (Connector X53 UPPER)
LED5	Green	LED is lit when USBH2 Host power is ON (Connector X53 LOWER)
LED6	Red	LED is lit when SoM and board is in a "RESET" state (CTRL_RESET_MOCI# is LOW).
LED7	Green	LED is lit when SD Card power is ON
LED8	Green	LED is lit when +V5 power is available
LED9	Green	LED is lit when +V5_SW power is available
LED10	Green	LED is lit when +V3.3_SW power is available
LED11	Green	LED is lit when +V1.2_SW power is available (Power for USB HUB and Ethernet_2 transceiver)
LED12	Green	LED is lit when +V1.8_SW power is available
LED13	Green	LED is lit when USB HUB power is ON
LED14	Green	Mini PCIe status indicator: WWAN. (Indication depend on the installed card)
LED15	Green	Mini PCIe status indicator: WLAN. (Indication depend on the installed card)
LED16	Green	Mini PCIe status indicator: WPAN. (Indication depend on the installed card)
LED17	Red	LED is lit when power supply input protection is fault due to the forward Overcurrent
LED18	Green	LED is lit when Mini PCIe connector power is ON
LED19	Green	LED is lit when Ethernet_2 transceiver power is ON
LED20	Green	LED is lit when Audio Codec power is ON
LED21	Green	User LED. It is lit when the LED_1 signal is High
LED22	Green	User LED. It is lit when the LED_2 signal is High
LED23	Green	User LED. It is lit when the LED_3 signal is High
LED24	Green	User LED. It is lit when the LED_4 signal is High
LED25	Green	LED is lit when +V5_STB (Development Board Standby power) is available
LED26	Green	LED is lit when USB Debugger (IC41) power is available - USB Debugger is connected to the PC
LED27	Yellow	FTDI JTAG activity
LED28	Yellow	LED is blinking when data transmission on FTDI_UARTC_3.3V_TXD occurs
LED29	Yellow	LED is blinking when data transmission on FTDI_UARTC_3.3V_RXD occurs
LED30	Yellow	LED is blinking when data transmission on FTDI_UARTD_3.3V_TXD occurs
LED31	Yellow	LED is blinking when data transmission on FTDI_UARTD_3.3V_RXD occurs
LED32	Green	LED is lit when the RS485 transceiver is ON
LED33	Green	LED is lit when RS232 "FORCEOFF" mode is disabled. Check RS232 datasheet for details

More details are available in the [Verdin Development Board Schematics](#)

2.6 Test Points

SMD and through-hole test points are available on the Verdin Development Board to allow customers to measure critical signals during the development and debugging process.

Figure 6: Verdin Development Board Test Points



The Test Points and their purposes are listed in the table below.

Table 16: Test Points

Designator	Description
TP1	SD Card Serial Data 0
TP2	SD Card Serial Data 1
TP3	SD Card Serial Data 2
TP4	SD Card Serial Data 3
TP5	SD Card Command Line
TP6	SD Card Serial Clock
TP7	SD Card Detection
TP8	SD Card Write Protection Input
TP9	SoM Power Supply Voltage

Continued on next page

Table 16: Test Points (Continued)

Designator	Description
TP10	
TP11	
TP12	
TP13	
TP14	
TP15	Through-hole test point pin (GND)
TP16	
TP17	
TP18	
TP19	
TP20	
TP21	SoM power supply current sensing resistor (High side)
TP22	SoM power supply current sensing resistor (Low side)
TP23	SD Card power supply
TP24	Open Drain "ALERT" output of the temperature sensing IC50
TP25	RLIN/GPIO3 pin of the Audio Codec IC28
TP26	Open Drain "VCONN_FAULT" output of the IC53 pulled up to +V1.8_SW with 100k resistor
TP27	Open Drain "OUT2" output of the IC53 for the current mode detection logic
TP28	Open Drain "OUT1" output of the IC53 for the current mode detection logic
TP29	Open Drain "DIR" output of the IC53 for the USB-C plug orientation indication
TP30	CSB/GPIO1 pin of the Audio Codec IC28
TP31	CDBUS2 pin of the universal USB converter IC41 (USB Debugger 3.3V RTS output)
TP32	CDBUS3 pin of the universal USB converter IC41 (USB Debugger 3.3V CTS input)
TP33	DDBUS2 pin of the universal USB converter IC41 (USB Debugger 3.3V RTS output)
TP34	DDBUS3 pin of the universal USB converter IC41 (USB Debugger 3.3V CTS input)
TP35	HDMI eARC differential line positive signal
TP36	HDMI eARC differential line negative signal
TP37	Ethernet_2 transceiver interrupt output. It can be used as a regular GPIO if R332 is removed
TP38	Ethernet_2 transceiver MDIO data signal. It can be used as a regular GPIO if R150 is removed
TP39	Ethernet_2 transceiver MDIO clock signal. It can be used as a regular GPIO if R147 is removed

2.7 Ethernet Interface

The Verdin Development Board provides 2x RJ45 connectors with integrated magnetics for 10/100/1000Mb Ethernet. The Ethernet_1 transceiver is located on the SoM while the Ethernet_2 transceiver is placed on the Verdin Development Board. Some modules do not feature both Ethernet interfaces. Please refer to the datasheet of the respective Verdin SoM.

2.7.1 Ethernet_1 Connector (X25)

Connector Type: RJ45, BEL A829-1J1T-KM / LINK-PP LPJK7436A98NL

Table 17: Ethernet_1 Connector (X25)

Pin	Signal name	SODIMM Pin	I/O Type	Voltage	Description
1	ETH_1_CTREF_2				Integrated magnetics center tap 2
2	ETH_1_MDI2_N	241	I/O (Analog)		Media Dependent Interface
3	ETH_1_MDI2_P	239	I/O (Analog)		Media Dependent Interface
4	ETH_1_MDI1_P	233	I/O (Analog)		Media Dependent Interface
5	ETH_1_MDI1_N	231	I/O (Analog)		Media Dependent Interface
6	ETH_1_CTREF_1				Integrated magnetics center tap 1
7	ETH_1_CTREF_3				Integrated magnetics center tap 3
8	ETH_1_MDI3_P	247	I/O (Analog)		Media Dependent Interface
9	ETH_1_MDI3_N	245	I/O (Analog)		Media Dependent Interface
10	ETH_1_MDI0_N	227	I/O (Analog)		Media Dependent Interface
11	ETH_1_MDI0_P	225	I/O (Analog)		Media Dependent Interface
12	ETH_1_CTREF_0				Integrated magnetics center tap 0
13	ETH_1_ACT_C	237	O (OD)		LED for indication Ethernet activity
14	+V3.3_SW		Power	+3.3V	Power supply for the indication LEDs
15	ETH_1_LINK_GB	235			LED for indication established Ethernet link
16	+V3.3_SW		Power	+3.3V	Power supply for the indication LEDs
17	ETH_1_LINK_C	235	O (OD)		LED for indication established Ethernet link
S1/S2	GND_CHASSIS		PWR		

2.7.2 Ethernet_2 Connector (X35)

The Ethernet_2 interface is based on the KSZ9131RNXI 10/100/1000 Mbps Ethernet PHY which is using ETH_2_RGMII interface of the module. For more information, refer to the KSZ9131RNX IC datasheet.

Connector Type: RJ45, BEL A829-1J1T-KM / LINK-PP LPJK7436A98NL

Table 18: Ethernet_2 Connector (X35)

Pin	Signal name	I/O Type	Voltage	Description
1	ETH_2_CTREF_2			Integrated magnetics center tap 2
2	ETH_2_MDI2_N	I/O (Analog)		Media Dependent Interface
3	ETH_2_MDI2_P	I/O (Analog)		Media Dependent Interface
4	ETH_2_MDI1_P	I/O (Analog)		Media Dependent Interface
5	ETH_2_MDI1_N	I/O (Analog)		Media Dependent Interface
6	ETH_2_CTREF_1			Integrated magnetics center tap 1
7	ETH_2_CTREF_3			Integrated magnetics center tap 3
8	ETH_2_MDI3_P	I/O (Analog)		Media Dependent Interface
9	ETH_2_MDI3_N	I/O (Analog)		Media Dependent Interface
10	ETH_2_MDI0_N	I/O (Analog)		Media Dependent Interface
11	ETH_2_MDI0_P	I/O (Analog)		Media Dependent Interface
12	ETH_2_CTREF_0			Integrated magnetics center tap 0

Continued on next page

Table 18: Ethernet_2 Connector (X35) (Continued)

Pin	Signal name	I/O Type	Voltage	Description
13	ETH_2_ACT_C	O (OD)		LED for indication Ethernet activity
14	+V3.3_SW	Power	+3.3V	Power supply for the indication LEDs
15	ETH_2_LINK_GB			LED for indication established Ethernet link
16	+V3.3_SW	Power	+3.3V	Power supply for the indication LEDs
17	ETH_2_LINK_C	O (OD)		LED for indication established Ethernet link
S1/S2	GND_CHASSIS	PWR		

2.8 Verdin USB_1 Port

The Verdin Development Board integrates a USB-C connector X34, connected to the Verdin USB_1 port (USB 2.0 interface only). This port is usually used in the recovery mode for loading new software onto the module and can work as a dual-role-port (DRP), which means Host or Device. This behaviour is similar to the On-The-Go (OTG) functionality, but the term USB OTG is only used in conjunction with the USB Micro-AB or the obsolete USB Mini-AB receptacle. ID pin is absent on the USB Type-C receptacle. The determination of Host or Device functionality is handled differently in Type-C using the configuration channel (CC) pins. The CC pins perform the same functions that the ID pin previously performed: they indicate the role of equipment as host, device, or both. The CC pins also detect if the connection is being made or if it is broken.

To handle all the operations required for the USB dual-role-port TUSB321AI chip has been used. It can function as an upstream-facing port (UFP), downstream-facing port (DFP), or a dual-role port (DRP) product based on a pin configuration. The device handles all aspects of the USB Type-C connection process (including the CC pins that mirror the micro-A/B ID pin behavior) to determine the port role. When connected as a peripheral (UFP), the TUSB321AI indicates the VBUS current provided by the attached host through the general-purpose input/output (GPIO) pins. When connected as a DFP, these devices advertise VBUS current to the attached peripheral. For the details, please check the [TUSB321AI datasheet](#).

On the Development Board, this port is configured as a dual-role port (DRP) by default, and its output current is limited to 1A.

2.8.1 USB_1 Connector (X34)

Connector Type: USB-C, Amphenol 12401598E4#2A

Table 19: USB_1 Connector (X34)

Pin	Signal name	SODIMM Pin	I/O Type	Voltage	Description
A1	GND		PWR		
A2	NC				Not connected
A3	NC				Not connected
A4	+V5_VBUS_USB_1	159	PWR	+5V	+5V USB power output
A5	USB_1_CC1				Type-C configuration channel signal 1
A6	USB_1_D_CON_P	165	I/O		Positive differential USB 2.0 Signal
A7	USB_1_D_CON_N	163	I/O		Negative differential USB 2.0 Signal
A8	NC				Not connected

Continued on next page

Table 19: USB_1 Connector (X34) (Continued)

Pin	Signal name	SODIMM Pin	I/O Type	Voltage	Description
A9	+V5_VBUS_USB_1	159	PWR	+5V	+5V USB power output
A10	NC				Not connected
A11	NC				Not connected
A12	GND		PWR		
B1	GND		PWR		
B2	NC				Not connected
B3	NC				Not connected
B4	+V5_VBUS_USB_1	159	PWR	+5V	+5V USB power output
B5	USB_1_CC2				Type-C configuration channel signal 1
B6	USB_1_D_CON_P	165	I/O		Positive differential USB 2.0 Signal
B7	USB_1_D_CON_N	163	I/O		Negative differential USB 2.0 Signal
B8	NC				Not connected
B9	+V5_VBUS_USB_1	159	PWR	+5V	+5V USB power output
B10	NC				Not connected
B11	NC				Not connected
B12	GND				
SH1/SH2	GND_CHASSIS		PWR		
SH3/SH4	GND_CHASSIS		PWR		

2.9 Verdin USB_2 Port

The Verdin Development Board integrates a 4 port USB hub (Microchip USB5744T-I/2G) connected the SoM's USB_2 port, providing 4x USB 3.x / USB 2.0 Host interfaces. The level of USB 3.x standard supported depends on the SoM. Some SoMs may not support USB 3.x interface at all. Refer to the respective [SoM datasheet](#) to get the detailed information about supported USB interfaces and their speed. The hub itself support USB 3.2 Gen 1 / USB 2.0 standards.

The naming schemes of USB 3.x (SuperSpeed) interface can be a bit confusing. There are different names for the same speed grade, depending on the revision of the specifications that are taken. In a table below a short comparison of the different transfer modes and their naming schemes has been done. Not all the USB 3.x transfer modes are possible with the Verdin modules, since in the Verdin standard only one lane of SuperSpeed signals are reserved.

Table 20: USB_3.x

Marketing Name	USB 3.2 Name	USB 3.1 Name	USB 3.0 Name	Nominal Speed	SuperSpeed Lanes	Supported by Verdin
SuperSpeed USB	USB 3.2 Gen 1x1	USB 3.2 Gen 1	USB 3.0	5 Gbit/s 0.5 GByte/s	1	Possible
SuperSpeed USB 10 Gbit/s	USB 3.2 Gen 1x2			10 Gbit/s 1 GByte/s	2	No
SuperSpeed USB 10 Gbit/s	USB 3.2 Gen 2x1	USB 3.1 Gen 2		10 Gbit/s 1.2 GByte/s	1	Possible
SuperSpeed USB 20 Gbit/s	USB 3.2 Gen 2x2			20 Gbit/s 2.4 GByte/s	2	No

The OC sensing pin of the USB_2 port is not used, and the USB hub handles OC conditions. Port 1 of the USB hub is disabled; on Port 4, only the USB 2.0 interface is used, and it is routed to the Mini PCIe connector (X33). Port 2 and Port 3 are routed to a stacked USB 3.0 Type-A connector (X53). Maximum data rate for this connector is 5Gbit/s. For further information about the USB hub, please refer to its [datasheet](#).

2.9.1 USB_2 Connector (X53)

Connector Type: Stacked USB 3.0 Type-A, Amphenol GSB311231HR (Pins starting with U connect to the UPPER, pins starting with L connect to the LOWER port)

Table 21: USB_2 Connector (X53)

Pin	Signal name	I/O Type	Voltage	Description
U1	+V5_VBUS_USBH3	PWR	+5V	+5V USB power output
U2	USBH3_D_CON_N	I/O		Negative differential USB 2.0 signal
U3	USBH3_D_CON_P	I/O		Positive differential USB 2.0 signal
U4	GND	PWR		
U5	USBH3_SSRX_CON_N	I		Negative differential USB 3.x receive signal
U6	USBH3_SSRX_CON_P	I		Positive differential USB 3.x receive signal
U7	GND	PWR		
U8	USBH3_SSTX_CON_N	O		Negative differential USB 3.x transmit signal
U9	USBH3_SSTX_CON_P	O		Positive differential USB 3.x transmit signal
L1	+V5_VBUS_USBH2	PWR	+5V	+5V USB power output
L2	USBH2_D_CON_N	I/O		Negative differential USB 2.0 signal
L3	USBH2_D_CON_P	I/O		Positive differential USB 2.0 signal
L4	GND	PWR		
L5	USBH2_SSRX_CON_N	I		Negative differential USB 3.x receive signal
L6	USBH2_SSRX_CON_P	I		Positive differential USB 3.x receive signal
L7	GND	PWR		
L8	USBH2_SSTX_CON_N	O		Negative differential USB 3.x transmit signal
L9	USBH2_SSTX_CON_P	O		Positive differential USB 3.x transmit signal
S1/S2	GND_CHASSIS	PWR		
S3/S4	GND_CHASSIS	PWR		

2.10 PCIe Interface

The Verdin Development Board makes the standard PCIe interface on the Verdin SoMs available on a Mini PCIe slot. PCI Express Mini Card is a replacement for the Mini PCI form factor. Mini PCIe provides both the standard PCI Express and USB 2.0 signals, allowing flexibility in peripheral design. PCI Express Mini Card edge connectors provide multiple connections and buses, such as listed below:

- PCI Express 1 lane (with SMBus)
- USB 2.0
- Indication LEDs for wireless network status
- SIM card for cellular applications (UIM signals)

2.10.1 Mini PCIe Connector (X33)

Connector Type: Mini PCIe Card Connector and Latch, Molex 67910-5700, 48099-5701

Table 22: Mini PCIe Connector (X33)

Pin	Signal name	SODIMM Pin	I/O Type	Voltage	Pull-up/Pull-down	Description
1	PCIE_1_WAKE#	252	O (OD)	+1.8V	5.1k to +V1.8_SW	Wake-up to SoM
3	NC					
5	NC					Not connected
7	NC					
9	GND		PWR			
11	PCIE_1_CLK_N	226	I			Negative differential PCIe reference clock signal
13	PCIE_1_CLK_P	228	I			Positive differential PCIe reference clock signal
15	GND		PWR			
17	NC					Not connected
19	NC					
21	GND		PWR			
23	PCIE_1_L0_RX_N	232	O			Negative differential PCIe receive signal
25	PCIE_1_L0_RX_P	234	O			Positive differential PCIe receive signal
27	GND		PWR			
29	GND		PWR			
31	PCIE_1_L0_TX_N	238	I			Negative differential PCIe transmit signal
33	PCIE_1_L0_TX_P	240	I			Positive differential PCIe transmit signal
35	GND		PWR			
37	GND		PWR			
39	+V3.3_PCIE_1		PWR	+3.3V		+3.3V Power input
41	+V3.3_PCIE_1		PWR	+3.3V		
43	GND		PWR			
45	NC					Not connected
47	NC					
49	NC					
51	NC					
2	+V3.3_PCIE_1		PWR	+3.3V		+3.3V Power input
4	GND		PWR			
6	+V1.5_PCIE_1		PWR	+1.5V		+1.5V Power input
8	PCIE_1_UIM_PWR		PWR			SIM Card Power
10	PCIE_1_UIM_DATA		I/O			SIM Card Data
12	PCIE_1_UIM_CLK		O			SIM Card Clock
14	PCIE_1_UIM_RESET		O			SIM Card RESET
16	PCIE_1_UIM_VPP		PWR			SIM Card Programming voltage
18	GND		PWR			

Continued on next page

Table 22: Mini PCIe Connector (X33) (Continued)

Pin	Signal name	SODIMM Pin	I/O Type	Voltage	Pull-up/Pull-down	Description
20	PCIE_1_WDISABLE#		I (OD)		47k to +V3.3_PCIE_1	PCIe Wireless interface disable
22	PERST#	244	I (OD)		10k to +V3.3_PCIE_1	PCIe Power enable/RESET
24	+V3.3_SW		PWR	+3.3V		+3.3V Standby power input
26	GND		PWR			
28	+V1.5_PCIE_1		PWR	+1.5V		+1.5V Power input
30	PCIE_1_SMCLK	12	I	+3.3V	10k to +V3.3_PCIE_1	PCIe SMBus Clock
32	PCIE_1_SMDAT	14	I/O	+3.3V	10k to +V3.3_PCIE_1	PCIe SMBus Data
34	GND		PWR			
36	USBH4_D_N	I/O				Negative differential USB 2.0 data signal
38	USBH4_D_P	I/O				Positive differential USB 2.0 data signal
40	GND		PWR			
42	PCIE_1_WWAN#	O (OD)				WWAN LED
44	PCIE_1_WLAN#	O (OD)				WLAN LED
46	PCIE_1_WPAN#	O (OD)				WPAN LED
48	+V1.5_PCIE_1		PWR	+1.5V		+1.5V Power input
50	GND		PWR			
52	+V3.3_PCIE_1		PWR	+3.3V		+3.3V Power input

2.10.2 SIM Card Holder (X36)

Connector Type: NANO SIM, Molex 1042240820

Table 23: SIM Card Holder (X36)

Pin	Signal name	I/O Type	Voltage	Pull-up/Pull-down	Description
S1	PCIE1_B_UIM_PWR	PWR			SIM Card Power
S2	PCIE1_B_UIM_RESET	I			SIM Card RESET
S3	PCIE1_B_UIM_CLK	I			SIM Card Clock
S4	GND	PWR			
S5	PCIE1_B_UIM_VPP	PWR			SIM Card Programming voltage
S6	PCIE1_B_UIM_DATA	I/O			SIM Card Data
G1/G2	GND	PWR			
G3/G4	GND	PWR			

2.11 SD Card Interface

The Verdin Development Board has a 4-bit SDIO interface and a hardware-supported card detection function (CD). SD Card write-protection status can be verified using the related [test points](#) on the board. The Verdin family supports SD Card Low Voltage Signalling mode. So, if the SD card itself also supports this mode, then communication will start at 3.3V and switch to 1.8V after the card has been initialized. The SD_1_PWR_EN signal allows to power ON and OFF SD the Card power supply (+V3.3_SD).

2.11.1 SD Card 4-bit Connector (X55)

Connector Type: SD Card, Würth 693063020911

Table 24: SD Card 4-bit Connector (X55)

Pin	Signal name	SODIMM Pin	I/O Type	Voltage	Pull-up/Pull-down	Description
1	SD_1_D3	72	I/O	+1.8/3.3V	Pull-up on a SoM	Serial Data 3
2	SD_1_CMD	74	I/O	+1.8/3.3V	Pull-up on a SoM	Command
3	GND		PWR			
4	+V3.3_SD		PWR	+3.3V		SD Card power input
5	SD_1_CLK	78	O	+1.8/3.3V		Serial Clock
6	GND		PWR			
7	SD_1_D0	80	I/O	+1.8/3.3V	Pull-up on a SoM	Serial Data 0
8	SD_1_D1	82	I/O	+1.8/3.3V	Pull-up on a SoM	Serial Data 1
9	SD_1_D2	70	I/O	+1.8/3.3V	Pull-up on a SoM	Serial Data 2
10	SD_1_CD#	84	I	+1.8/3.3V	Pull-up on a SoM	Card Detect
11	SD1_WP	(TP8)	I			Write Protection

2.12 Display Interface

The Verdin Development Board provides two options for connecting LCD panels and monitors via the following two interfaces supported:

- HDMI
- MIPI DSI

Almost any TFT display can be connected to the Verdin module by HDMI port X37 or via the DSI interface connector X48. X48 features a universal mezzanine board connector. This solution allows for connecting various types of display interface mezzanine boards and converters, e.g., DSI to HDMI, DSI to LVDS, DSI to RGB, etc. Custom boards with the appropriate MIPI DSI connector can also be used.

2.12.1 HDMI Connector (X37)

Connector Type: HDMI Connector Right Angle, Amphenol 10029449-111RLF

Table 25: HDMI Connector (X37)

Pin	Signal name	SODIMM Pin	I/O Type	Voltage	Pull-up/Pull-down	Description
1	HDMI_1_TXD2_CON_P	87	O			HDMI/DVI differential data lane 2, positive
2	GND		PWR			
3	HDMI_1_TXD2_CON_N	85	O			HDMI/DVI differential data lane 2, negative
4	HDMI_1_TXD1_CON_P	81	O			HDMI/DVI differential data lane 1, positive
5	GND		PWR			
6	HDMI_1_TXD1_CON_N	79	O			HDMI/DVI differential data lane 1, negative
7	HDMI_1_TXD0_CON_P	75	O			HDMI/DVI differential data lane 0, positive

Continued on next page

Table 25: HDMI Connector (X37) (Continued)

Pin	Signal name	SODIMM Pin	I/O Type	Voltage	Pull-up/Pull-down	Description
8	GND		PWR			
9	HDMI_1_TXD0_CON_N	73	O			HDMI/DVI differential data lane 0, negative
10	HDMI_1_TXC_CON_P	69	O			HDMI/DVI differential clock positive
11	GND		PWR			
12	HDMI_1_TXC_CON_N	67	O			HDMI/DVI differential clock negative
13	HDMI_1_CEC_CON	63	I/O	+5V	27k to +V3.3_SW	HDMI Consumer Electronic Control
14	HDMI_1_HEC_CON	NC				
15	HDMI_1_DDC_SCL	59	O	+5V	1.8k to +V5_HDMI_1_DISP	DDC Interface Clock
16	HDMI_1_DDC_SDA	57	I/O	+5V	1.8k to +V5_HDMI_1_DISP	DDC Interface Data
17	GND		PWR			
18	+V5_HDMI_1_DISP		PWR	+5V		HDMI power out
19	HDMI_1_HPD_CON	61	I	+5V		Hot Plug Detect
S1/S2	GND_CHASSIS		PWR			
S3/S4	GND_CHASSIS		PWR			

2.12.2 DSI Display Adapter Connector (X48)

Connector Type: Samtec LSS-130-03-L-DV-A-K-TR

Table 26: DSI Display Adapter Connector (X48)

Pin	Signal name	SODIMM Pin	I/O Type	Voltage	Pull-up/Pull-down	Description
1	NC					Not connected
3	GND		PWR			
5	NC					Not connected
7	+V_SUPPLY_FILT_SW		PWR	7-24V ±10%		
9	+V_SUPPLY_FILT_SW		PWR	7-24V ±10%		
11	+V_SUPPLY_FILT_SW		PWR	7-24V ±10%		7-24V power supply output
13	+V_SUPPLY_FILT_SW		PWR	7-24V ±10%		
15	+V_SUPPLY_FILT_SW		PWR	7-24V ±10%		
17	NC					Not connected
19	+V5_SW		PWR	+5V		
21	+V5_SW		PWR	+5V		
23	+V5_SW		PWR	+5V		+5V power supply output
25	+V5_SW		PWR	+5V		
27	+V5_SW		PWR	+5V		
29	NC					Not connected
31	+V3.3_SW		PWR	+3.3V		
33	+V3.3_SW		PWR	+3.3V		+3.3V power supply output

Continued on next page

Table 26: DSI Display Adapter Connector (X48) (Continued)

Pin	Signal name	SODIMM Pin	I/O Type	Voltage	Pull-up/Pull-down	Description
35	+V3.3_SW		PWR	+3.3V		+3.3V power supply output
37	+V3.3_SW		PWR	+3.3V		
39	+V3.3_SW		PWR	+3.3V		
41	NC					Not connected
43	+V1.8_SW		PWR	+1.8V		+1.8V power supply output
45	+V1.8_SW		PWR	+1.8V		
47	+V1.8_SW		PWR	+1.8V		
49	+V1.8_SW		PWR	+1.8V		
51	+V1.8_SW		PWR	+1.8V		
53	NC					Not connected
55	GND		PWR			
57	CTRL_RESET_MOCI#		O (OD)	+1.8V	10k to +V3.3_SW	Board peripheral RESET
59	DSI_1_PWR_EN		O	+1.8V		DSI Adapter power enable
2	NC					Not connected
4	I2C_1_SDA	12	I/O	+1.8V	1.8k to +V1.8_SW	Generic I ² C bus Data
6	I2C_1_SCL	14	O	+1.8V	1.8k to +V1.8_SW	Generic I ² C bus Clock
8	GPIO_9_DSI	17	I/O	+1.8V		Dedicated general-purpose IO for the DSI display adapters
10	GND		PWR			
12	DSI_1_D0_P	49	I/O			DSI Interface differential data lane 0, positive
14	DSI_1_D0_N	47	I/O			DSI Interface differential data lane 0, negative
16	GND		PWR			
18	DSI_1_D1_P	43	O			DSI interface differential data lane 1, positive
20	DSI_1_D1_N	41	O			DSI interface differential data lane 1, negative
22	GND		PWR			
24	DSI_1_CLK_P	37	O			DSI interface differential clock, positive
26	DSI_1_CLK_N	35	O			DSI interface differential clock, negative
28	GND		PWR			
30	DSI_1_D2_P	31	O			DSI interface differential data lane 2, positive
32	DSI_1_D2_N	29	O			DSI interface differential data lane 2, negative
34	GND		PWR			
36	DSI_1_D3_P	25	O			DSI Interface differential data lane 3, positive
38	DSI_1_D3_N	23	O			DSI Interface differential data lane 3, negative
40	GND		PWR			
42	I2S_2_BCLK	42	O	+1.8V		Serial audio bit clock
44	I2S_2_SYNC	44	O	+1.8V		Synchronization/ field select/ left-right channel select
46	I2S_2_D_OUT	46	O	+1.8V		Serial audio output data
48	I2S_2_D_IN	48	I	+1.8V		Serial audio input data

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Table 26: DSI Display Adapter Connector (X48) (Continued)

Pin	Signal name	SODIMM Pin	I/O Type	Voltage	Pull-up/Pull-down	Description
50	GND		PWR			
52	I2C_2_DSI_SCL	55	O	+1.8V	1.8k to +V1.8_SW	DSI adapters DDC Clock
54	I2C_2_DSI_SDA	53	I/O	+1.8V	1.8k to +V1.8_SW	DSI adapters DDC Data
56	GPIO_10_DSI	21	I/O	+1.8V		Dedicated general-purpose I/O for DSI display adapters
58	PWM_3_DSI	19	O	+1.8V		DSI Display adapters PWM brightness control
60	GND		PWR			

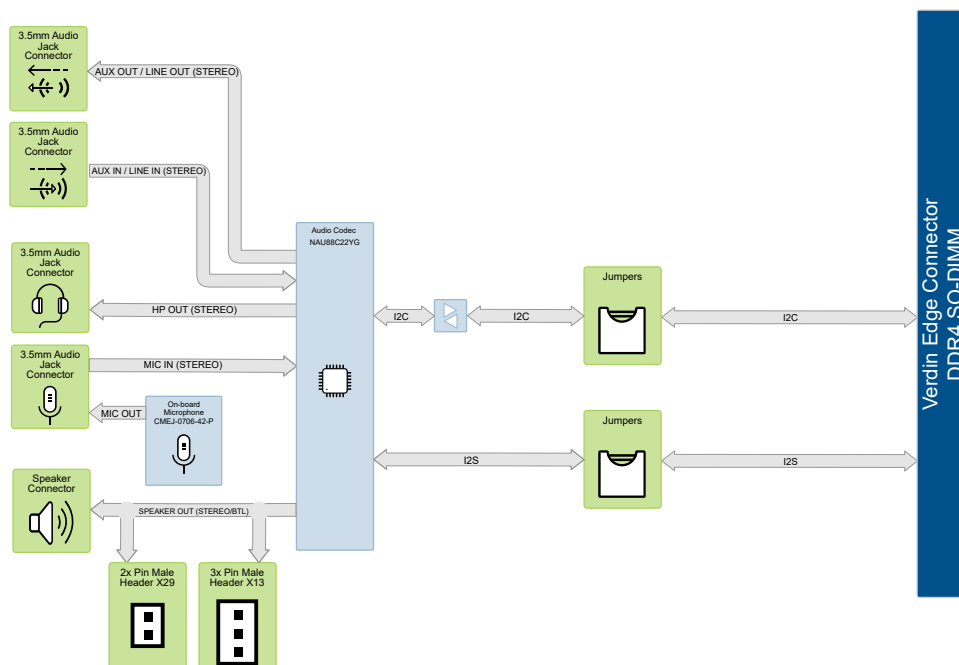
2.13 Audio

The Verdin Development Board offers two audio interfaces: an analog audio interface and a digital audio interface (routed to DSI display adapter connector X48).

2.13.1 Analog Audio

The analog audio interface is based on the NAU88C22YG audio codec IC from Nuvoton. The analog audio interfaces are available on connectors X14, X20, X21, X22, which are standard 3.5mm stereo connectors for AUX OUT, HEADPHONE OUT, AUX IN, and MIC IN. The NAU88C22YG audio codec IC also contains a speaker driver, and its output is available on connectors X13, X28, X29.

Figure 7: Analog Audio Architecture



2.13.1.1 AUX OUT Audio Jack (X14)

Connector Type: 3.5mm Jack, CUI SJ1-3535NG

Table 27: AUX OUT Audio Jack (X14)

Pin	Signal name	I/O Type	Voltage	Pull-up/Pull-down	Description
1	GND	PWR			
2	AAP_AUXOUT2_CON	O (Analog)		4.7k to GND	Auxiliary output 2 / Line out Left
3	AAP_AUXOUT1_CON	O (Analog)		4.7k to GND	Auxiliary output 1 / Line out Right
4	NC				Not connected
5	NC				Not connected

2.13.1.2 AUX IN Audio Jack (X21)

Connector Type: 3.5mm Jack, CUI SJ1-3535NG-BE

Table 28: AUX IN Audio Jack (X21)

Pin	Signal name	I/O Type	Voltage	Pull-up/Pull-down	Description
1	GND	PWR			
2	AAP_AUXIN_CON_L	I (Analog)		47k to GND	Auxiliary input 2 / Line input Left
3	AAP_AUXIN_CON_R	I (Analog)		47k to GND	Auxiliary input 1 / Line input Right
4	NC				Not connected
5	NC				

2.13.1.3 HEADPHONES OUT Audio Jack (X20)

Connector Type: 3.5mm Jack, CUI SJ1-3535NG-GR

Table 29: HEADPHONES OUT Audio Jack (X20)

Pin	Signal name	I/O Type	Voltage	Pull-up/Pull-down	Description
1	GND	PWR			
2	AAP_HP_CON_L	O (Analog)		10k to GND	Headphones output Left
3	AAP_HP_CON_R	O (Analog)		10k to GND	Headphones output Right
4	NC			Not connected	Not connected
5	AAP_LLIN_CON_GPIO2		+1.8V	47k to +V1.8_AAP_VDDB	Headphones connect detection

2.13.1.4 MIC IN Audio Jack (X22)

Connector Type: 3.5mm Jack, CUI SJ1-3535NG-PI

Table 30: MIC IN Audio Jack (X22)

Pin	Signal name	I/O Type	Voltage	Pull-up/Pull-down	Description
1	GND	PWR			
2	AAP_LMIC_CON_P	I		2.2k to AAP_MICBIAS	Microphone input Left
3	AAP_RMIC_CON_P	I		2.2k to AAP_MICBIAS	Microphone input Right

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Table 30: MIC IN Audio Jack (X22) (Continued)

Pin	Signal name	I/O Type	Voltage	Pull-up/Pull-down	Description
4	AAP_MIC_1_OUT	O			On-board microphone output
5	GND	PWR			

Microphone MIC1, located on the board, is be used when the external microphone is disconnected

2.13.1.5 SPEAKER OUT 3-pin Header (X13)

Connector Type: 1×3 Pin Header Male, 2.54 mm pitch

Table 31: SPEAKER OUT 3-pin header (X13)

Pin	Signal name	I/O Type	Voltage	Pull-up/Pull-down	Description
1	AAP_SPKOUT_CON_R	O		47k to GND	Right speaker output
2	GND	PWR			
3	AAP_SPKOUT_CON_L	O		47k to GND	Left speaker output

2.13.1.6 SPEAKER OUT 2-pin Header (X29)

Connector Type: 1×2 Pin Header Male, 2.54 mm pitch

Table 32: SPEAKER OUT 2-pin header (X29)

Pin	Signal name	I/O Type	Voltage	Pull-up/Pull-down	Description
1	AAP_SPKOUT_R	O			BTL ¹ Speaker Positive Output
2	AAP_SPKOUT_L	O			BTL ¹ Speaker Negative Output

2.13.1.7 SPEAKER OUT Connector (X28)

Connector Type: 1×2 Terminal block, CUI TBLH10-500-02BK

Table 33: SPEAKER OUT Connector (X28)

Pin	Signal name	I/O Type	Voltage	Pull-up/Pull-down	Description
1	AAP_SPKOUT_R	O			BTL ¹ Speaker Positive Output
2	AAP_SPKOUT_L	O			BTL ¹ Speaker Negative Output

¹ BTL – Bridge-Tied-Load speaker output configuration. The two channels of a stereo amplifier are fed the same monaural audio signal, with one channel's electrical polarity reversed. A loudspeaker is connected between the two amplifier outputs, bridging the output terminals. This doubles the available voltage swing at the load compared with the same amplifier used without bridging.

2.13.2 Digital Audio

Digital audio on the Verdin Development Board is available as an I²S interface (I²S_2). It is provided on the X48 connector (MIPI DSI interface) to provide the option of using an audio interface along with display solutions. For detailed information, refer to the X48 connector pinout.

2.14 "Module-specific" Interface

The "Module-specific" mezzanine board connector provides access to the "Module-specific" interfaces on the Verdin SoM. The range of available interfaces depends on the Verdin module being used. For this reason, "Module-specific" (MSP) signals can be both differential pairs or single-ended signals. All potential differential signals are routed as differential lines with impedance control (100 Ohm for differential and 55 Ohm for single-ended) and equal length. This allows them to be used for any high-speed interface a module may provide.

"Module-specific" mezzanine boards are available for most Verdin SoMs and are connected to this interface to provide access to the "Module-specific" features of those SoMs. Please refer to the datasheets of the individual "Module-specific" mezzanine boards and respective Verdin SoMs for more information.

Customers are free to develop their own "Module-specific" mezzanine boards for prototyping and development purposes. If high-speed differential signals available on MSP pins are used in a custom application, then stitching capacitors should be placed on single-ended MSP signal lines (please check the schematic of the Verdin Development Board). The stitching capacitors provide a return path for the MSP differential signal's currents, improving signal integrity and reducing EMI.

2.14.1 "Module-specific" Mezzanine Board Connector (X52)

Connector Type: Samtec LSS-150-03-L-DV-A-K-TR

Table 34: "Module-specific" Mezzanine Board Connector (X52)

Pin	Signal name	SODIMM Pin	I/O Type	Voltage	Pull-up/Pull-down	Description
1	PWR_1V8_MOCI	214	PWR	+1.8V		+1.8V SoM power output, 250 mA max
3	GND		PWR			
5	MSP_39/40_P	180	I/O			MSP interface differential pair 39/40 positive signal
7	MSP_39/40_N	178	I/O			MSP interface differential pair 39/40 negative signal
9	MSP_38	176	I/O			MSP interface single-ended signal 38
11	MSP_36/37_P	174	I/O			MSP interface differential pair 36/37 positive signal
13	MSP_36/37_N	172	I/O			MSP interface differential pair 36/37 negative signal
15	GND		PWR			
17	MSP_34/35_P	168	I/O			MSP interface differential pair 34/35 positive signal
19	MSP_34/35_N	166	I/O			MSP interface differential pair 34/35 negative signal
21	MSP_33	164	I/O			MSP interface single-ended signal 33
23	MSP_31/32_P	162	I/O			MSP interface differential pair 31/32 positive signal
25	MSP_31/32_N	160	I/O			MSP interface differential pair 31/32 negative signal
27	GND		PWR			
29	MSP_29/30_P	156	I/O			MSP interface differential pair 29/30 positive signal

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Table 34: "Module-specific" Mezzanine Board Connector (X52) (Continued)

Pin	Signal name	SODIMM Pin	I/O Type	Voltage	Pull-up/Pull-down	Description
31	MSP_29/30_N	154	I/O			MSP interface differential pair 29/30 negative signal
33	MSP_28	152	I/O			MSP interface single-ended signal 28
35	MSP_26/27_P	150	I/O			MSP interface differential pair 26/27 positive signal
37	MSP_26/27_N	148	I/O			MSP interface differential pair 26/27 negative signal
39	GND		PWR			
41	MSP_24/25_P	144	I/O			MSP interface differential pair 24/25 positive signal
43	MSP_24/25_N	142	I/O			MSP interface differential pair 24/25 negative signal
45	MSP_23	140	I/O			MSP interface single-ended signal 23
47	MSP_21/22_P	138	I/O			MSP interface differential pair 21/22 positive signal
49	MSP_21/22_N	136	I/O			MSP interface differential pair 21/22 negative signal
51	GND		PWR			
53	MSP_19/20_P	132	I/O			MSP interface differential pair 19/20 positive signal
55	MSP_19/20_N	130	I/O			MSP interface differential pair 19/20 negative signal
57	MSP_18	128	I/O			MSP interface single-ended signal 18
59	MSP_16/17_P	126	I/O			MSP interface differential pair 16/17 positive signal
61	MSP_16/17_N	124	I/O			MSP interface differential pair 16/17 negative signal
63	GND		PWR			
65	MSP_14/15_P	120	I/O			MSP interface differential pair 14/15 positive signal
67	MSP_14/15_N	118	I/O			MSP interface differential pair 14/15 negative signal
69	MSP_13	116	I/O			MSP interface single-ended signal 13
71	MSP_11/12_P	114	I/O			MSP interface differential pair 11/12 positive signal
73	MSP_11/12_N	112	I/O			MSP interface differential pair 11/12 negative signal
75	GND		PWR			
77	MSP_9/10_P	108	I/O			MSP interface differential pair 9/10 positive signal
79	MSP_9/10_N	106	I/O			MSP interface differential pair 9/10 negative signal
81	MSP_8	104	I/O			MSP interface single-ended signal 8
83	MSP_6/7_P	102	I/O			MSP interface differential pair 6/7 positive signal

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Table 34: "Module-specific" Mezzanine Board Connector (X52) (Continued)

Pin	Signal name	SODIMM Pin	I/O Type	Voltage	Pull-up/Pull-down	Description
85	MSP_6/7_N	100	I/O			MSP interface differential pair 6/7 negative signal
87	GND		PWR			
89	MSP_4/5_P	96	I/O			MSP interface differential pair 4/5 positive signal
91	MSP_4/5_N	94	I/O			MSP interface differential pair 4/5 negative signal
93	MSP_3	92	I/O			MSP interface single-ended signal 3
95	MSP_1/2_P	90	I/O			MSP interface differential pair 1/2 positive signal
97	MSP_1/2_N	88	I/O			MSP interface differential pair 1/2 negative signal
99	GND		PWR			
2	GND		PWR			
4	MSP_44/45_P	192	I/O			MSP interface differential pair 44/45 positive signal
6	MSP_44/45_N	190	I/O			MSP interface differential pair 44/45 negative signal
8	MSP_43	188	I/O			MSP interface single-ended signal 43
10	MSP_41/42_P	186	I/O			MSP interface differential pair 41/42 positive signal
12	MSP_41/42_N	184	I/O			MSP interface differential pair 41/42 negative signal
14	GND		PWR			
16	I2C_4_CSI_SCL	95	O	+1.8V	1.8k to +V1.8_SW	CSI Camera I ² C bus Clock
18	I2C_4_CSI_SDA	93	I/O	+1.8V	1.8k to +V1.8_SW	CSI Camera I ² C bus Data
20	SODIMM_222 (GPIO_8_CSI)	222	I/O	+1.8V		General-purpose I/Os, dedicated for the MIPI CSI camera interface
22	SODIMM_220 (GPIO_7_CSI)	220	I/O	+1.8V		
24	SODIMM_218 (GPIO_6_CSI)	218	I/O	+1.8V		
26	SODIMM_216 (GPIO_5_CSI)	216	I/O	+1.8V		
28	GPIO_4	212	I/O	+1.8V		General-purpose I/O
30	GPIO_3	210	I/O	+1.8V		General-purpose I/O
32	GPIO_2	208	I/O	+1.8V		General-purpose I/O
34	GPIO_1	206	I/O	+1.8V		General-purpose I/O
36	MSP_CSI_1_MCLK	91	O	+1.8V		CSI camera master clock
38	CTRL_RESET_MOCI#	258	O (OD)	+3.3V	10k to +V3.3_SW	General reset signal
40	CTRL_SLEEP_MOCI#	256	O	+1.8V		
42	CTRL_PWR_EN_MOCI	254	O	+1.8V		General power enable signal
44	CTRL_WAKE1_MICO#	252	I	+1.8V	5.1k to +V1.8_SW	
46	SPI_1_CS	202	O	+1.8V		SPI Slave Select

Continued on next page

Table 34: "Module-specific" Mezzanine Board Connector (X52) (Continued)

Pin	Signal name	SODIMM Pin	I/O Type	Voltage	Pull-up/Pull-down	Description
48	SPI_1_MOSI	200	O	+1.8V		SPI Master Output, Slave Input
50	SPI_1_MISO	198	I	+1.8V		SPI Master Input, Slave Output
52	SPI_1_CLK	196	O	+1.8V		SPI Serial Clock
54	I2C_1_SCL	14	O	+1.8V	1.8k to +V1.8_SW	Generic I ² C bus Clock
56	I2C_1_SDA	12	I/O		1.8k to +V1.8_SW	Generic I ² C bus Data
58	PWR_CTRL_10		O	+1.8V		MSP mezzanine board power enable
60	+V1.8_SW		PWR	+1.8V		+1.8V power supply output
62	+V1.8_SW		PWR	+1.8V		
64	+V3.3_SW		PWR	+3.3V		+3.3V power supply output
66	+V3.3_SW		PWR	+3.3V		
68	+V5_SW		PWR	+5V		+5V power supply output
70	+V5_SW		PWR	+5V		
72	+V_SUPPLY_FILT_SW		PWR	7-24V ±10%		7-24V ±10% power supply output
74	+V_SUPPLY_FILT_SW		PWR	7-24V ±10%		
76	GND		PWR			
78	I2S_2_D_IN	48	I	+1.8V		Serial audio input data
80	I2S_2_D_OUT	46	O	+1.8V		Serial audio output data
82	I2S_2_SYNC	44	O	+1.8V		Synchronization/ field select/ left-right channel select
84	I2S_2_BCLK	42	O	+1.8V		Serial audio bit clock
86	SODIMM_21 (GPIO_10_DSI)	21	I/O	+1.8V		General-purpose IOs, dedicated for the MIPI DSI display adapters
88	SODIMM_17 (GPIO_9_DSI)	17	I/O	+1.8V		
90	SODIMM_19 (PWM_3_DSI)	19	I/O	+1.8V		PWM output, dedicated for the MIPI DSI display backlight brightness control
92	PWM_2	16	O	+1.8V		General-purpose PWM outputs
94	PWM_1	15	O	+1.8V		
96	GND		PWR			
98	I2C_2_DSI_SCL	55	O	+1.8V	1.8k to +V1.8_SW	DSI adapters DDC Clock
100	I2C_2_DSI_SDA	53	I/O	+1.8V	1.8k to +V1.8_SW	DSI adapters DDC Data

2.15 MIPI CSI Camera Interface

The MIPI CSI Camera Interface on connector X47 is intended for applications requiring image capture capability from CMOS or CDD image sensors. For details, please see the relevant Verdin module datasheet.

2.15.1 MIPI CSI Camera Connector (X47)

Connector Type: 24 Position FFC, FPC, vertical 0.5mm, Hirose FH12-24S-0.5SVA(54)

Table 35: MIPI CSI Camera Connector (X47)

Pin	Signal name	SODIMM Pin	I/O Type	Voltage	Pull-up/Pull-down	Description
1	GND		PWR			
2	CSI_1_D0_CON_N	125	I/O			CSI differential data lane 0, negative
3	CSI_1_D0_CON_P	123	I/O			CSI differential data lane 0, positive
4	GND		PWR			
5	CSI_1_D1_CON_N	119	I			CSI differential data lane 1, negative
6	CSI_1_D1_CON_P	117	I			CSI differential data lane 1, positive
7	GND		PWR			
8	CSI_1_CLK_CON_N	113	I			CSI differential clock, negative
9	CSI_1_CLK_CON_P	111	I			CSI differential clock, positive
10	GND		PWR			
11	CAM_1_CON_RST	216	O			Camera RESET
12	CSI_1_MCLK	91	O			CSI camera master clock
13	I2C_4_CSI_CON_SCL	95	O	+3.3V	10k to +V3.3_SW	CSI Camera I ² C bus Clock
14	I2C_4_CSI_CON_SDA	93	I/O	+3.3V	10k to +V3.3_SW	CSI Camera I ² C bus Data
15	+V3.3_SW		PWR	+3.3V		+3.3V power out
16	CSI_1_D2_CON_N	107	I			CSI differential data lane 2, negative
17	CSI_1_D2_CON_P	105	I			CSI differential data lane 2, positive
18	GND		PWR			
19	CSI_1_D3_CON_N	101	I			CSI differential data lane 3, negative
20	CSI_1_D3_CON_P	99	I			CSI differential data lane 3, positive
21	+V5_SW		PWR	+5V		+5V power output
22	CAM_1_CON_PWRDWN	218	O	+3.3V		Camera Power Down
23	CAM_1_CON_IC_DETECT	220	I	+3.3V		Camera Identification
24	CAM_1_CON_PWRCTRL	222	O	+3.3V		Power Supply Control

2.16 Digital and Analog I/O

2.16.1 Communication Interface

2.16.1.1 CAN

The Verdin Development Board uses the Texas Instruments isolated ISO1042BDWR CAN transceiver to implement two CAN FD interfaces in conjunction with the two CAN interface on the Verdin module.

CAN ports are electrically isolated from the system power supply and provide an isolated 5V power supply output with a load capacity of 126 mA for each port.

The CAN interfaces are available on connectors X59 and X60. Pin header-to-DSUB9 adapters can be used with X59, X60 connectors.

The jumpers JP1, JP2, JP3, JP4 provide hardware configuration for these interfaces:

Connector Type: 1×2 Pin Header Male, 2.54 mm pitch

Table 36: Jumpers for CAN Interface

Jumper	Status	Function
JP1, JP2	CLOSED	CAN1 split terminated.
JP3, JP4	CLOSED	CAN2 split terminated.

By default, the jumpers JP1, JP2, JP3, JP4 are closed.

2.16.1.1.1 CAN1 Connector (X59)

Connector Type: 2×5 Pin Header Male, 2.54 mm pitch

Table 37: CAN1 Connector (X59)

Pin	Signal Name	I/O Type	Voltage	Description
1	NC			Not connected
2	CAN_1_PGND	PWR		CAN_1 isolated GND
3	CAN_1_L	I/O		Low-level CAN_1 bus line
4	CAN_1_H	I/O		High-level CAN_1 bus line
5	GND_CAN_1_ISO			Connected through 100 Ohm
6	NC			Not connected
7	NC			Not connected
8	CAN_1_PWR	PWR	+5V	CAN_1 isolated power out
9	NC			Not connected
10	NC			Not connected

2.16.1.1.2 CAN2 Connector (X60)

Connector Type: 2×5 Pin Header Male, 2.54 mm pitch

Table 38: CAN2 Connector (X60)

Pin	Signal Name	I/O Type	Voltage	Description
1	NC			Not connected
2	CAN_2_PGND	PWR		CAN_2 isolated GND
3	CAN_2_L	I/O		Low-level CAN_2 bus line
4	CAN_2_H	I/O		High-level CAN_2 bus line
5	GND_CAN_2_ISO			Connected through 100 Ohm
6	NC			Not connected
7	NC			Not connected
8	CAN_2_PWR	PWR	+5V	CAN_2 isolated power out
9	NC			Not connected

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Table 38: CAN2 Connector (X60) (Continued)

Pin	Signal Name	I/O Type	Voltage	Description
10	NC			Not connected

2.16.1.2 UART Interfaces

The Verdin Development Board features 4 UART interfaces that are connected to the following connectors:

- UART1 to the connector X50 through an RS485 transceiver.
- UART2 to the connector X51 through an RS232 transceiver.
- UART3 to a built-in USB to Serial transceiver (Primary debug log output for Cortex-A cores).
- UART4 to a built-in USB to Serial transceiver (Primary debug log output for Cortex-M core).

2.16.1.2.1 RS485 Connector (X50)

Connector Type: D-Sub 9 Male, Assmann WSW A-DS 09 A/KG-T4S

Table 39: RS485 Connector (X50)

Pin	Signal Name	I/O Type	Voltage	Description
1	GND	PWR		
2	NC			
3	NC			
4	NC			Not connected
5	NC			
6	NC			
7	NC			
8	RS485_CON_A	I/O		Digital bus I/O, A
9	RS485_CON_B	I/O		Digital bus I/O, B
S1/S2	GND_CHASSIS			

Jumpers JP6, JP9, and JP10 provide hardware configuration for this interface:

Connector Type: 1×2 Pin Header Male, 2.54 mm pitch

Table 40: Jumpers for RS485

Jumper	Status	Function
JP6	CLOSED	The slew rate is reduced to 250 kbps. The default is 20 Mbps.
JP9	CLOSED	Insert the 120ohm bus termination for RS485
JP10	CLOSED	ECHO disabled (the sender cannot read the message just sent)

By default, the jumpers JP6, JP9, JP10 are closed.

2.16.1.2.2 RS232 Connector (X51)

Connector Type: D-Sub 9-pin Male, Assmann WSW A-DS 09 A/KG-T4S

Table 41: RS232 Connector (X51)

Pin	Signal Name	I/O Type	Voltage	Description
1	NC			Not connected
2	RS232_RXD	I		RS232 Receive Data
3	RS232_TXD	O		RS232 Transmit Data
4	NC			Not connected
5	GND	PWR		
6	NC			Not connected
7	RS232_RTS	O		RS232 Request to Send (RTS)
8	RS232_CTS	I		RS232 Clear to Send (CTS)
9	NC			Not connected
S1/S2	GND_CHASSIS			

By using the jumper JP12, it is possible to configure the Auto Powerdown Plus function of the RS232 transceiver. The following table shows the JP12 connection possibilities.

Connector Type: 1×3 Pin Header Male, 2.54 mm pitch

Table 42: Jumpers for RS232

Jumper position	Description
1 - 2	Auto Powerdown Plus disabled
2 - 3	Auto Powerdown Plus enabled

By default, the jumper JP12 is installed in position 1-2.

For detailed information about the Auto Powerdown Plus function, please refer to the [TRS3122ERGER transceiver datasheet](#) (FORCEON and FORCEOFF# pins functions).

2.17 Digital Interfaces

2.17.1 Switches / LEDs

The Verdin Development Board features four general-purpose green LEDs, four general-purpose switches, and four general-purpose buttons. Pins of these devices are available on connectors X23, X24, X26, X27, and X38 (See Figure 8 and 9). They can be directly connected to the GPIO breakout connectors or specific custom hardware. Please note that the buttons and switches are not de-bounced.

2.17.1.1 Switches Connector (X23)

Connector Type: 1×2 Pin Header Female, 2.54 mm pitch, Samtec SSW-102-01-G-S

Table 43: Switch Connector (X23)

Pin	Signal Name	I/O Type	Voltage	Pull-up/Pull-down
1	SW_4	O	+1.8V	100k to GND
2	SW_8	O	+1.8V	10k to GND

2.17.1.2 Switches Connector (X24)

Connector Type: 1×2 Pin Header Female, 2.54 mm pitch, Samtec SSW-102-01-G-S

Table 44: Switch Connector (X24)

Pin	Signal Name	I/O Type	Voltage	Pull-up/Pull-down
1	SW_5	O	+1.8V	100k to GND
2	SW_9	O	+1.8V	10k to GND

2.17.1.3 Switches Connector (X26)

Connector Type: 1×2 Pin Header Female, 2.54 mm pitch, Samtec SSW-102-01-G-S

Table 45: Switch Connector (X26)

Pin	Signal Name	I/O Type	Voltage	Pull-up/Pull-down
1	SW_6	O	+1.8V	100k to GND
2	SW_10	O	+1.8V	10k to +V1.8_SW

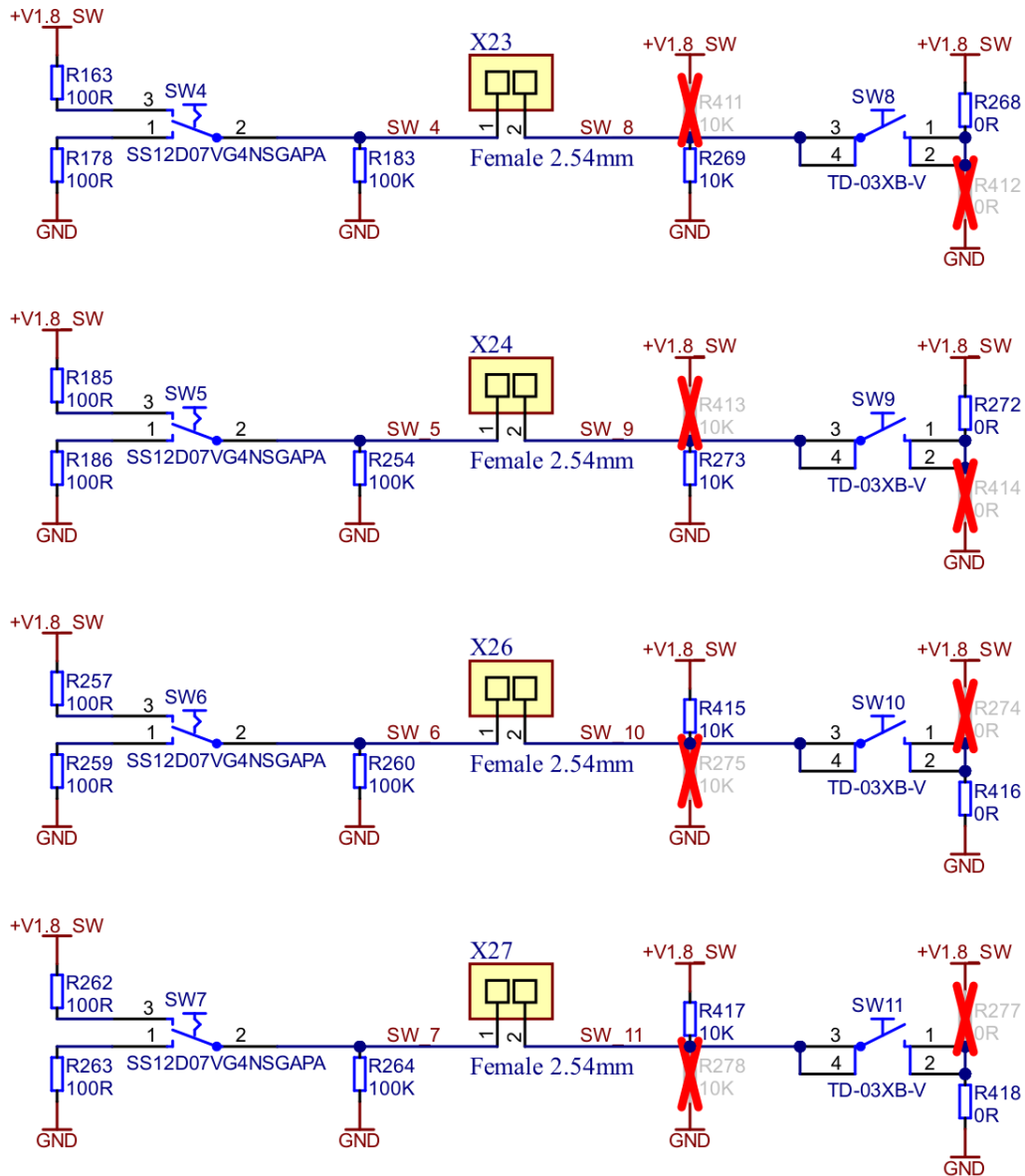
2.17.1.4 Switches Connector (X27)

Connector Type: 1×2 Pin Header Female, 2.54 mm pitch, Samtec SSW-102-01-G-S

Table 46: Switch Connector (X27)

Pin	Signal Name	I/O Type	Voltage	Pull-up/Pull-down
1	SW_7	O	+1.8V	100k to GND
2	SW_11	O	+1.8V	10k to +V1.8_SW

Figure 8: General-purpose Switches' Schematic



2.17.1.5 LEDs Connector (X38)

Connector Type: 1x2 Pin Header Female, 2.54 mm pitch, Samtec SSW-102-01-G-S

Table 47: LED Connector (X38)

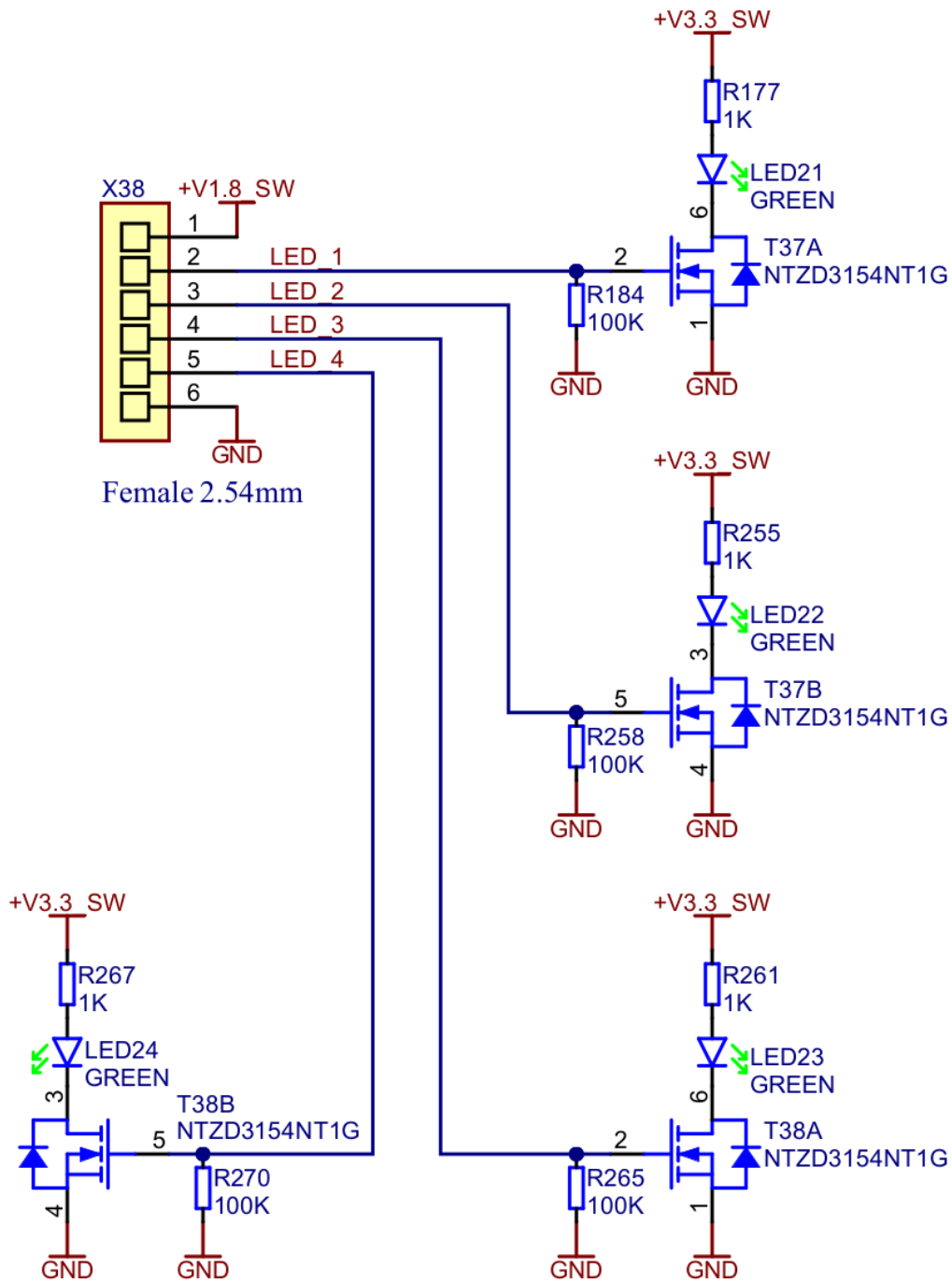
Pin	Signal Name	Linked LED	I/O Type	Voltage	Pull-up/Pull-down
1	+V1.8_SW	-	O	+1.8V	
2	LED_1	LED21	I	+1.8V	100k to GND
3	LED_2	LED22	I	+1.8V	100k to GND
4	LED_3	LED23	I	+1.8V	100k to GND
5	LED_4	LED24	I	+1.8V	100k to GND

Continued on next page

Table 47: LED Connector (X38) (Continued)

Pin	Signal Name	Linked LED	I/O Type	Voltage	Pull-up/Pull-down
6	GND	-	PWR	+1.8V	

Figure 9: General-purpose LEDs' Schematic



2.17.2 Level Shifters

Two level-shifters with push-pull outputs (IC31, IC 32) and one with open-drain outputs (IC33) have been placed on the Verdin Development Board. The I/O pins of these level shifters are connected to female pin headers X39, X40. These general-purpose level shifters can be used to connect external 3.3V compatible hardware with the jumper wires.

2.17.2.1 Level Shifter Connector (X39)

Connector Type: 1×10 Pin Header Female, 2.54 mm pitch

Table 48: Level Shifter Connector (X39)

Pin	Signal Name	I/O Type	Voltage	Pull-up/Pull-down	Description
1	LS_1.8V_GPIO_1	I	+1.8V	100k to GND	General-purpose 1.8V level-shifted inputs
2	LS_1.8V_GPIO_2	I	+1.8V	100k to GND	
3	LS_1.8V_GPIO_3	I	+1.8V	100k to GND	
4	LS_1.8V_GPIO_4	I	+1.8V	100k to GND	
5	LS_1.8V_GPIO_5	O	+1.8V		General-purpose 1.8V level-shifted outputs
6	LS_1.8V_GPIO_6	O	+1.8V		
7	LS_1.8V_GPIO_7	O	+1.8V		
8	LS_1.8V_GPIO_8	O	+1.8V		
9	LS_1.8V_SCL	I/O (OD)	+1.8V	10k to +V1.8_SW	General-purpose 1.8V level-shifted bidirectional Inputs/Outputs with an Open Drain (OD) configuration
10	LS_1.8V_SDA	I/O (OD)	+1.8V	10k to +V1.8_SW	

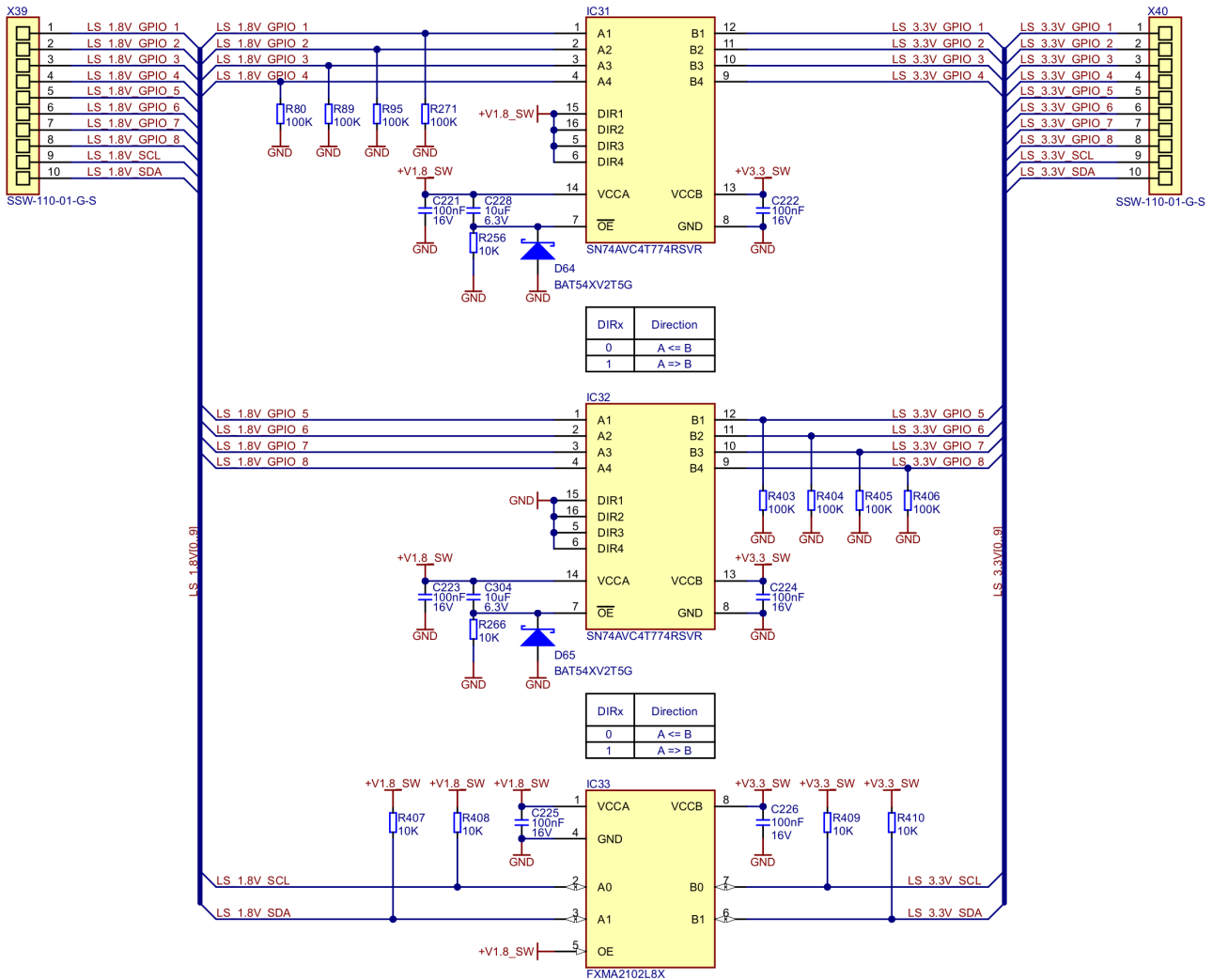
2.17.2.2 Level Shifter Connector (X40)

Connector Type: 1×10 Pin Header Female, 2.54 mm pitch

Table 49: Level Shifter Connector (X40)

Pin	Signal Name	I/O Type	Voltage	Pull-up/Pull-down	Description
1	LS_3.3V_GPIO_1	O	+3.3V		General-purpose 3.3V level-shifted outputs
2	LS_3.3V_GPIO_2	O	+3.3V		
3	LS_3.3V_GPIO_3	O	+3.3V		
4	LS_3.3V_GPIO_4	O	+3.3V		
5	LS_3.3V_GPIO_5	I	+3.3V	100k to GND	General-purpose 3.3V level-shifted inputs
6	LS_3.3V_GPIO_6	I	+3.3V	100k to GND	
7	LS_3.3V_GPIO_7	I	+3.3V	100k to GND	
8	LS_3.3V_GPIO_8	I	+3.3V	100k to GND	
9	LS_3.3V_SCL	I/O (OD)	+3.3V	10k to +V3.3_SW	General-purpose 3.3V level-shifted bidirectional Inputs/Outputs with an Open Drain (OD) configuration
10	LS_3.3V_SDA	I/O (OD)	+3.3V	10k to +V3.3_SW	

Figure 10: General-purpose Level Shifters' Schematic



2.17.3 Analog Interface

The Analog inputs of a Verdin module are connected to the dedicated connector X49. For detailed information about ADC features, please refer to the respective Verdin module datasheet.

2.17.3.1 ADC Input (X49)

Connector Type: 2×3 Pin Header Female, 2.54mm pitch

Table 50: ADC Input (X49)

Pin	Signal Name	SODIMM Pin	I/O Type	Voltage	Description
1	ADC_1	2	I (Analog)	+1.8V	Analog Input 1
2	ADC_2	4	I (Analog)	+1.8V	Analog Input 2
3	ADC_3	6	I (Analog)	+1.8V	Analog Input 3

Continued on next page

Table 50: ADC Input (X49) (Continued)

Pin	Signal Name	SODIMM Pin	I/O Type	Voltage	Description
4	ADC_4	8	I (Analog)	+1.8V	Analog Input 4
5	GND		PWR		
6	PWR_1V8_MOCI	214	PWR	+1.8V	SoM's 1.8V Power Output

2.18 Backup Battery

A backup battery holder (BAT1) is available on the Verdin Development Board to provide backup power to the RTC of a Verdin module when the main power is turned off. Jumper (JP8) is used to connect or disconnect the backup battery.

Connector Type: 1×2 Pin Header Male, 2.54 mm pitch

Table 51: Jumpers for Backup Battery

Pin	Status	Description
JP8	CLOSED	Battery backup voltage, connected to the Verdin module internal RTC.
JP8	OPEN	Battery backup voltage, disconnected to the Verdin module internal RTC.

By default, jumper JP8 is closed.

For more details on how the backup voltage is used, please refer to the respective Verdin computer-on-module datasheet.

2.18.1 Battery Holder (BAT1)

A 20 mm (diameter) coin cell/battery should be used with the Battery Holder (BAT1). A coin-cell battery can be used to provide power backup to the Verdin module RTC circuit when an external power supply is not available. Supported batteries: CR2032 or compatible coin-cell batteries.

Connector Type: Renata HU2032-LF

Table 52: Battery Holder (BAT1)

Pin	Description	Voltage
1	+V_BAT	+3.0V
2	GND	

2.19 Temperature Sensor

Verdin Development Board provides the Digital Temperature Sensor feature (IC50) with an I²C interface. The sensor is connected to the general-purpose I2C_1 bus. The default I²C address of the sensor is 0×4F. For details, please check the [TMP75CIDGKR sensor datasheet](#).

2.20 EEPROM

A 2-Kbit EEPROM (IC29) with a I²C interface is installed on the Development Board. The EEPROM can be used to store important data or for board identification. For EEPROM's technical details, please check

the [M24C02-FMN6TP datasheet](#). The EEPROM is accessible at the address 0x57 on the generic serial bus I2C_1.

Jumper JP5 can be used to control the EEPROM's "Write Protection" function.

Connector Type: 1x3 Pin Header Male, 2.54 mm pitch

Table 53: Jumpers for EEPROM

Jumper Position	Description
1-2	EEPROM's "Write Control" (WC) pin is driven "High". Write operations are disabled to the entire memory array.
2-3	EEPROM's "Write Control" (WC) pin is driven "Low". Write operations are enabled.

By default, jumper JP5 is in position 1-2.

2.21 JTAG

The Verdin Development Board provides a JTAG interface to the JTAG port available on Verdin modules. Connector X56 provides an interface to an external JTAG device via a Cortex Debug Connector, which is a 10-pin 1.27mm header. The Verdin Development Board also has an on-board JTAG debugger feature. Please check the USB Debugger section of this datasheet and the Verdin Development Board schematic file for detailed information. This document is available on the Toradex developer website, on the [Development Board Design page](#).



If an external JTAG debugger is used with a Verdin Development Board, jumpers X67A – X67F should be removed. Simultaneous use of the on-board and external JTAG Debugger is not allowed. Violating this requirement may damage the debugger or the Verdin Development Board.

2.21.1 JTAG Connector (X56)

Connector Type: 2x5 Pin Shrouded Header Male, 1.27mm, Samtec FTSH-105-01-L-DV-K

Table 54: JTAG Connector (X56)

Pin	Signal Name	SODIMM Pin	I/O Type	Voltage	Pull-up/Pull-down	Description
1	JTAG_1_VREF	7	PWR	+1.8V		1.8V reference output for JTAG adapter
2	JTAG_1_TMS	13	I	+1.8V		Test Mode Select
3	GND		PWR			
4	JTAG_1_TCK	9	I	+1.8V	Pull-down on SoM	Test Clock
5	GND		PWR			
6	JTAG_1_TDO	5	O	+1.8V		Test Data Out
7	NC					
8	JTAG_1_TDI	1	I	+1.8V		Test Data In
9	NC					
10	JTAG_1_TRST#	3	I (OD)	+1.8V		Test Reset

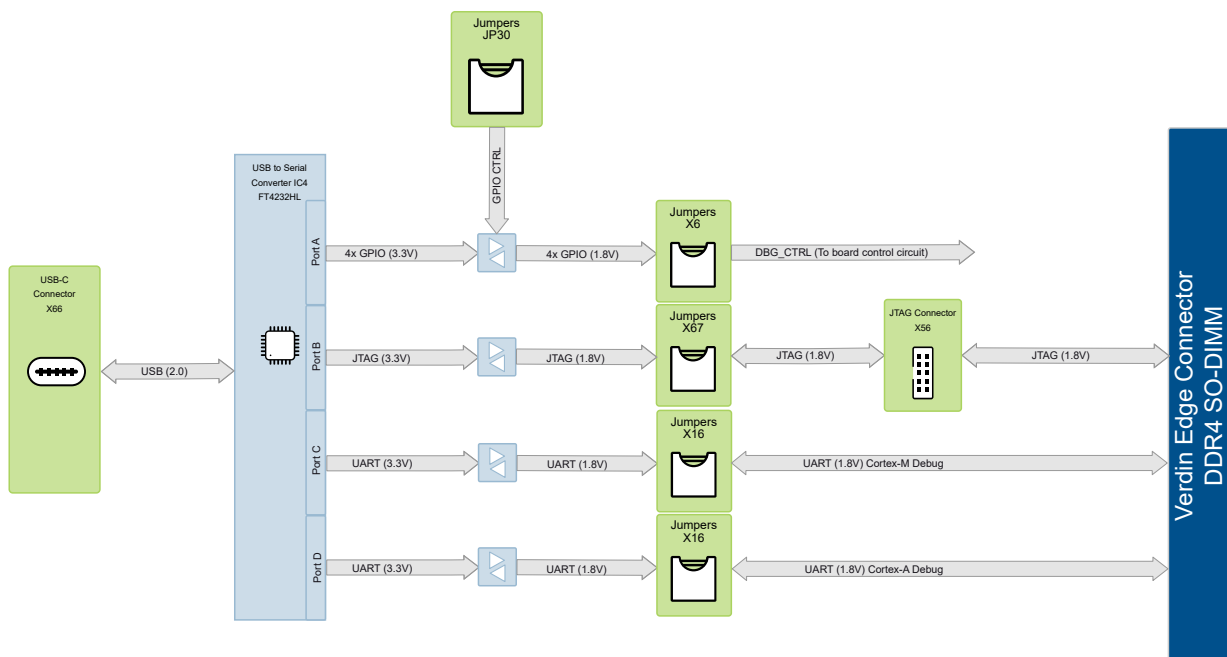
2.22 USB Debugger

The Verdin Development Board provides an on-board Universal USB Debugger (IC41). The debugger is based on the FT4232HL chip and provides the following features:

- 2x UART ports connected to Verdin Module Cortex-A and Cortex-M core debug outputs
- JTAG Debugger/Programmer
- 4x GPIO used for performing basic Development Board control features: Power ON/OFF, Reset etc.

Simplified USB Debugger architecture is shown below.

Figure 11: USB Debugger architecture



The pin assignments of the FT4232HL are shown in the table below.

Table 55: FT4232HL pin assignments

Pin	Pin Name	I/O Type	Interface	Connected/Controlled Net	Description
21	ADBUS4	O	GPIO	CTRL_FORCE_OFF_MOCI#	Verdin Development Board FORCE OFF
22	ADBUS5	O		CTRL_RESET_MICO#	Verdin Module RESET
23	ADBUS6	O		PWR_BTN#	Verdin Development Board POWER ON/OFF
24	ADBUS7	O		CTRL_RECOVERY_MICO#	Verdin Module RECOVERY mode
26	BDBUS0	O	JTAG	JTAG_1_TCK	JTAG Test Mode Select
27	BDBUS1	O		JTAG_1_TDI	JTAG Test Data Input
28	BDBUS2	I		JTAG_1_TDO	JTAG Test Data Output

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Table 55: FT4232HL pin assignments (Continued)

Pin	Pin Name	I/O Type	Interface	Connected/Controlled Net	Description
29	BDBUS3	O		JTAG_1_TMS	JTAG Test Mode Set
30	BDBUS4	O	JTAG	JTAG_1_TRST#	JTAG Test Mode Reset
34	BDBUS7	O		JTAG_1_LED	JTAG activity LED
38	CDBUS0	O	UART	UART_4_RXD	Receiver Data of Cortex-M debug UART
39	CDBUS1	I		UART_4_TXD	Transmitter Data of Cortex-M debug UART
48	DDBUS0	O	UART	UART_3_RXD	Receiver Data of Cortex-A debug UART
52	DDBUS1	I		UART_3_TXD	Transmitter Data of Cortex-A debug UART

The debug interface is accessible via the separate USB-C connector X66.

2.2.2.1 USB Debugger Connector (X66)

Connector Type: USB-C, Amphenol 12401598E4#2A

Table 56: USB Debugger Connector (X66)

Pin	Signal Name	I/O Type	Voltage	Pull-up/Pull-down	Description
A1	GND	PWR			
A2	NC				Not Connected
A3	NC				
A4	+V5_DBG	PWR	+5V		FTDI debugger power supply input
A5	USB_DBG_CC1			5.1k to GND	Type-C configuration channel signal 1
A6	USB_DBG_CON_P	I/O			Positive Differential USB 2.0 Signal
A7	USB_DBG_CON_N	I/O			Negative Differential USB 2.0 Signal
A8	NC				Not Connected
A9	+V5_DBG	PWR	+5V		FTDI debugger power supply input
A10	NC				Not Connected
A11	NC				
A12	GND	PWR			
B1	GND	PWR			
B2	NC				Not Connected
B3	NC				
B4	+V5_DBG	PWR	+5V		FTDI debugger power supply input
B5	USB_DBG_CC2			5.1k to GND	Type-C configuration channel signal 2
B6	USB_DBG_CON_P	I/O			Positive Differential USB 2.0 Signal
B7	USB_DBG_CON_N	I/O			Negative Differential USB 2.0 Signal
B8	NC				Not Connected
B9	+V5_DBG	PWR	+5V		FTDI debugger power supply input
B10	NC				Not Connected
B11	NC				

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Table 56: USB Debugger Connector (X66) (Continued)

Pin	Signal Name	I/O Type	Voltage	Pull-up/Pull-down	Description
B12	GND			PWR	
SH1/SH2	GND_CHASSIS				
SH3/SH4	GND_CHASSIS				

2.22.1.1 Jumper Area (X67)

Connector type: 2×6 Pin Header Male, 2.54 mm pitch

Table 57: Jumper Area (X67)

Signal Name	I/O Type	Pin	Pin	I/O Type	Signal Name	Voltage
FTDI_JTAG_TCK	O	B1	A1	I	JTAG_1_TCK	+1.8V
FTDI_JTAG_TDI	O	B2	A2	I	JTAG_1_TDI	+1.8V
FTDI_JTAG_TDO	I	B3	A3	O	JTAG_1_TDO	+1.8V
FTDI_JTAG_TMS	O	B4	A4	I	JTAG_1_TMS	+1.8V
FTDI_JTAG_TRST#	O	B5	A5	I	JTAG_1_TRST#	+1.8V
+VREF_JTAG_FTDI	PWR	B6	A6	PWR	JTAG_1_VREF	+1.8V

By changing the configuration of the jumpers X67A-X67F, the user can connect or disconnect the on-board JTAG Debugger to/from the SoM.

Connector type: 2×6 Pin Header Male, 2.54 mm pitch

Table 58: Jumpers for JTAG Debugger

Jumper	Status	Function
X67A, X67B, X67C, X67D, X67E, X67F	CLOSED	FTDI JTAG. Debugger connected to SoM
X67A, X67B, X67C, X67D, X67E, X67F	OPEN	FTDI JTAG. Debugger disconnected from SoM

By default, jumpers X67A, X67B, X67C, X67D, X67E, X67F are closed.



If an external JTAG debugger is used with a Verdin Development Board, jumpers X67A – X67F should be removed. Simultaneous use of the on-board and external JTAG Debugger is not allowed. Violating this requirement may damage the debugger or the Verdin Development Board.

The FTDI GPIO pins are connected via the X6 pin header. For details, please refer to the X6 pinout.

The FTDI GPIO pins can be used to control the Development Board or as regular GPIO (outputs only) to control other parts of the board

Jumper JP30 should be configured according to the desired FTDI GPIO pins functionality. Possible configurations are listed in the table below.

Connector type: 1×3 Pin Header Male, 2.54 mm pitch

Table 59: Jumpers for FTDI GPIO

Jumper Position	Description
1 - 2	FTDI GPIO pins can be used to control Verdin Development Board modes.
2 - 3	FTDI GPIO pins can be used as regular GPIO (outputs only)

By default, jumper JP30 is installed in position 1-2.

2.23 Low-Speed IO Pins Configuration

The Low-speed IO pins' breakout connectors offer the flexibility to map the IO pins of the Verdin module to either the on-board function or to external hardware. The factory setting is a straight-through jumper setting, meaning that the X3-A row is connected straight to the X3-B row. This is also true for the connectors X6 and X16. All signals residing on the male header are also available on a female connector in parallel to allow easy measurement, probing, and re-routing. To map the SODIMM pin with the corresponding SoC ball name, which is specific to individual Verdin modules, please refer to the applicable Verdin module datasheet.

2.23.1 Low-Speed IO Pins 1 Male (X3 Row A and B)

Connector type: Type: 2×30Pin Male, 2.54mm

Table 60: Low-speed IO pins 2 Male (X3 Row A and B)

SoM Side		Peripheral Side			I/O Type	Voltage	Pull-up/Pull-down	Description
SODIMM Pin	Signal Name	Pin	Pin	Signal Name				
12	SODIMM_12	A1	B1	I2C_1_SDA	I/O	+1.8V	1.8k to +V1.8_SW	Generic I ² C Data
14	SODIMM_14	A2	B2	I2C_1_SCL	O	+1.8V	1.8k to +V1.8_SW	Generic I ² C Clock
15	SODIMM_15	A3	B3	PWM_1	O	+1.8V		General-purpose PWM
16	SODIMM_16	A4	B4	PWM_2	O	+1.8V		
20	SODIMM_20	A5	B5	CAN_1_TX	O	+1.8V	10k to +V1.8_SW	CAN port 1 transmit pin
22	SODIMM_22	A6	B6	CAN_1_RX	I	+1.8V		CAN port 1 receive pin
24	SODIMM_24	A7	B7	CAN_2_TX	O	+1.8V	10k to +V1.8_SW	CAN port 2 transmit pin
26	SODIMM_26	A8	B8	CAN_2_RX	I	+1.8V		CAN port 2 receive pin
	GND	A9	B9	GND	PWR			
	+V1.8_SW	A10	B10	+V1.8_SW	PWR	+1.8V		+1.8V power supply output
30	SODIMM_30	A11	B11	I2S_1_BCLK	O	+1.8V		I ² S Serial Clock (Transmit Bit Clock)
32	SODIMM_32	A12	B12	I2S_1_SYNC	O	+1.8V		I ² S Field Select (Transmit Frame Sync)
34	SODIMM_34	A13	B13	I2S_1_D_OUT	O	+1.8V		I ² S Data Output
36	SODIMM_36	A14	B14	I2S_1_D_IN	I	+1.8V		I ² S Data Input
38	SODIMM_38	A15	B15	I2S_1_MCLK	O	+1.8V		I ² S Master clock output
	GND	A16	B16	GND	PWR			
42	SODIMM_42	A17	B17	I2S_2_BCLK	O	+1.8V		I ² S Serial Clock (Transmit Bit Clock)
44	SODIMM_44	A18	B18	I2S_2_SYNC	O	+1.8V		I ² S Field Select (Transmit Frame Sync)
46	SODIMM_46	A19	B19	I2S_2_D_OUT	O	+1.8V		I ² S Data Output
48	SODIMM_48	A20	B20	I2S_2_D_IN	I	+1.8V		I ² S Data Input
52	SODIMM_52	A21	B21	QSPI_1_CLK	O	+1.8V		QSPI Serial Clock
54	SODIMM_54	A22	B22	QSPI_1_CS#	O	+1.8V		QSPI Chip Select 0

Continued on next page

Table 60: Low-speed IO pins 2 Male (X3 Row A and B) (Continued)

SoM Side		Peripheral Side			I/O Type	Voltage	Pull-up/Pull-down	Description
SODIMM Pin	Signal Name	Pin	Pin	Signal Name				
56	SODIMM_56	A23	B23	QSPI_1_IO0	I/O	+1.8V	QSPI Serial I/Os for command, address, and data	
58	SODIMM_58	A24	B24	QSPI_1_IO1	I/O	+1.8V		
60	SODIMM_60	A25	B25	QSPI_1_IO2	I/O	+1.8V		
62	SODIMM_62	A26	B26	QSPI_1_IO3	I/O	+1.8V	QSPI Serial I/Os for command, address, and data	
64	SODIMM_64	A27	B27	QSPI_1_CS2#	O	+1.8V	QSPI Chip Select 1	
66	SODIMM_66	A28	B28	QSPI_1_DQS	I	+1.8V	QSPI Data Strobe signal	
76	SODIMM_76	A29	B29	SD_1_PWR_EN	O	+1.8V	100k to GND	SD card power rail enable
84	SODIMM_84	A30	B30	SD_1_CD#	I	+1.8V +3.3V	10k to +1.8/3.3V on SoM	SD Card Detection

2.23.2 Low-Speed IO Pins 1 Female (X2)

Connector type: 1×30Pin Female, 2.54mm

Pinout identical to X3 Pins A1 to A30

2.23.3 Function 1 Female (X4)

Connector type: 1×30Pin Female, 2.54mm

Pinout identical to X3 Pins B1 to B30

2.23.4 Low-Speed IO Pins 2 Male (X6 Row A and B)

Connector type: 2×30Pin Male

Table 61: Low-speed IO pins 2 Male (X6 Row A and B)

SoM Side		Peripheral Side			I/O Type	Voltage	Pull-up/Pull-down	Description
SODIMM Pin	Signal Name	Pin	Pin	Signal Name				
196	SODIMM_196	A1	B1	SPI_1_CLK	O	+1.8V	SPI Serial Clock	
198	SODIMM_198	A2	B2	SPI_1_MISO	O	+1.8V	SPI Master Input, Slave Output	
200	SODIMM_200	A3	B3	SPI_1_MOSI	O	+1.8V	SPI Master Output, Slave Input	
202	SODIMM_202	A4	B4	SPI_1_CS	O	+1.8V	SPI Slave Select	
	GND	A5	B5	GND	PWR			
206	SODIMM_206	A6	B6	GPIO_1	I/O	+1.8V	General-purpose I/Os	
208	SODIMM_208	A7	B7	GPIO_2	I/O	+1.8V		
210	SODIMM_210	A8	B8	GPIO_3	I/O	+1.8V		
212	SODIMM_212	A9	B9	GPIO_4	I/O	+1.8V		
214	SODIMM_PWR_1V8_MOCI	A10	B10	PWR_1V8_MOCI	PWR	+1.8V	+1.8V SoM power output	
216	SODIMM_216	A11	B11	GPIO_5_CSI	O	+1.8V	100k to GND	General-purpose I/Os dedicated for the CSI camera interface
218	SODIMM_218	A12	B12	GPIO_6_CSI	O	+1.8V	100k to GND	
220	SODIMM_220	A13	B13	GPIO_7_CSI	I	+1.8V		
222	SODIMM_222	A14	B14	GPIO_8_CSI	O	+1.8V	100k to GND	
	GND	A15	B5	GND	PWR			
216	FTDI_GPIOL3	A16	B16	DBG_RECOVERY#	I	+1.8V	10k to +V1.8_DBG	SoM RECOVERY mode debugger control input
218	FTDI_GPIOL2	A17	B17	DBG_PWR_BTN#	I	+1.8V	10k to +V1.8_DBG	Board POWER button debugger control input
220	FTDI_GPIOL1	A18	B18	DBG_RESET#	I	+1.8V	10k to +V1.8_DBG	General board RESET debugger control input
222	FTDI_GPIOL0	A19	B19	DBG_FORCE_OFF#	I	+1.8V	10k to +V1.8_DBG	General board FORCE OFF debugger control input
	+V1.8_SW	A20	B20	+V1.8_SW	PWR	+1.8V		+1.8V Power supply output
246	SODIMM_246	A21	B21	CTRL_RECOVERY_MICO#	I (OD)	+1.8V		SoM RECOVERY mode control
248	SODIMM_248	A22	B22	CTRL_PWR_BTN_MICO#	I	+1.8V		SoM POWER button control input

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Table 61: Low-speed IO pins 2 Male (X6 Row A and B) (Continued)

SoM Side		Peripheral Side			I/O Type	Voltage	Pull-up/Pull-down	Description
SODIMM Pin	Signal Name	Pin	Pin	Signal Name				
250	SODIMM_250	A23	B23	CTRL_FORCE_OFF_MOCI#	O	+1.8V	100k to +V5_STB	General board FORCE OFF control
252	SODIMM_252	A24	B24	CTRL_WAKE1_MICO#	I	+1.8V	5.1k to +V1.8_SW	Wake-capable signal to resume SoM from SLEEP mode
254	SODIMM_254	A25	B25	CTRL_PWR_EN_MOCI	O	+1.8V	100k to GND	Power enable for the on-board peripherals
256	SODIMM_256	A26	B26	CTRL_SLEEP_MOCI#	O	+1.8V		Sleep signal for the on-board peripherals
258	SODIMM_258	A27	B27	CTRL_RESET_MOCI#	O	+3.3V	10k to +V3.3_SW	Reset for the on-board peripherals
260	SODIMM_260	A28	B28	CTRL_RESET_MICO#	I (OD)	+1.8V		SoM's RESET signal
	GND	A29	B29	GND	PWR			
196	+V1.8_SW	A30	B30	+V1.8_SW	PWR	+1.8V		+1.8V Power supply output

2.23.5 Function 2 Female (X5)

Connector Type: 1×30Pin Female, 2.54mm Pinout identical to X6 Pins A1 to A30

2.23.6 Low-Speed IO Pins 2 Female (X7)

Connector Type: 1×30Pin Female, 2.54mm Pinout identical to X6 Pins B1 to B30

2.23.7 Low-Speed IO Pins 3 Male (X16 Row A and B)

Connector Type: 2×30 Pin Male

Table 62: Low-speed IO pins 2 Male (X16 Row A and B)

SoM Side		Peripheral Side			I/O Type	Voltage	Pull-up/Pull-down	Description
SODIMM Pin	Signal Name	Pin	Pin	Signal Name				
187	SODIMM_187	A1	B1	USB_2_OC#	I/(OD)	+1.8V	100k to +V1.8_SW	USB_2 interface overcurrent condition signal
185	SODIMM_185	A2	B2	USB_2_EN	O	+1.8V	100k to GND	USB_2 interface power supply enable signal
161	SODIMM_161	A3	B3	USB_1_ID	I	+1.8V	100k to +V1.8_SW	ID pin if USB_1 port used in OTG mode
157	SODIMM_157	A4	B4	USB_1_OC#	I	+1.8V	100k to +V1.8_SW	USB_1 interface overcurrent condition signal
155	SODIMM_155	A5	B5	USB_1_EN	O	+1.8V	100k to GND	USB_1 interface power supply enable signal
95	SODIMM_95	A6	B6	I2C_4_CSI_SCL	O	+1.8V	10k to +V1.8_SW	CSI Camera control I ² C bus Clock
93	SODIMM_93	A7	B7	I2C_4_CSI_SDA	I/O	+1.8V	10k to +V1.8_SW	CSI Camera control I ² C bus Data
91	SODIMM_91	A8	B8	CSI_1_MCLK	O	+1.8V		CSI Camera Master Clock
63	SODIMM_63	A9	B9	HDMI_1_CEC	I/O	+1.8V	10k to +V1.8_SW	HDMI Consumer Electronic Control
61	SODIMM_61	A10	B10	HDMI_1_HPD	I	+1.8V		HDMI Hot Plug Detect
59	SODIMM_59	A11	B11	I2C_3_HDMI_SCL	O	+1.8V	10k to +V1.8_SW	HDMI DDC Clock
57	SODIMM_57	A12	B12	I2C_3_HDMI_SDA	I/O	+1.8V	10k to +V1.8_SW	HDMI DDC Data
153	SODIMM_153	A13	B13	UART_4_TXD	O	+1.8V	10k to +V1.8_SW	Cortex-M debug UART data transmit
151	SODIMM_151	A14	B14	UART_4_RXD	I	+1.8V		Cortex-M debug UART data receive
149	SODIMM_149	A15	B15	UART_3_TXD	O	+1.8V	10k to +V1.8_SW	Cortex-A debug UART data transmit
147	SODIMM_147	A16	B16	UART_3_RXD	I	+1.8V		Cortex-A debug UART data receive
55	SODIMM_55	A17	B17	I2C_2_DSI_SCL	O	+1.8V	1.8k to +V1.8_SW	DSI display adapter DDC Clock
53	SODIMM_53	A18	B18	I2C_2_DSI_SDA	I/O	+1.8V	1.8k to +V1.8_SW	DSI display adapter DDC Data
21	SODIMM_21	A19	B19	GPIO_10_DSI	I/O	+1.8V		Dedicated general-purpose I/O reserved for DSI display adapters
19	SODIMM_19	A20	B20	PWM_3_DSI	O	+1.8V		DSI Display adapters PWM brightness control
17	SODIMM_17	A21	B21	GPIO_9_DSI	I/O	+1.8V		Dedicated general-purpose I/O reserved for DSI display adapters
143	SODIMM_143	A22	B22	UART_2_CTS	I	+1.8V		UART_2 Clear to Send (CTS)

Continued on next page

Table 62: Low-speed IO pins 2 Male (X16 Row A and B) (Continued)

SoM Side		Peripheral Side			I/O Type	Voltage	Pull-up/Pull-down	Description
SODIMM Pin	Signal Name	Pin	Pin	Signal Name				
141	SODIMM_141	A23	B23	UART_2_RTS	O	+1.8V		UART_2 Request to Send (RTS)
139	SODIMM_139	A24	B24	UART_2_TXD	O	+1.8V		UART_2 Transmit Data
137	SODIMM_137	A25	B25	UART_2_RXD	I	+1.8V		UART_2 Receive Data
135	SODIMM_135	A26	B26	UART_1_CTS	I	+1.8V		UART_1 Clear to Send (CTS)
133	SODIMM_133	A27	B27	UART_1_RTS	O	+1.8V	10k to +V1.8_SW	UART_1 Request to Send (RTS)
131	SODIMM_131	A28	B28	UART_1_TXD	O	+1.8V		UART_1 Transmit Data
129	SODIMM_129	A29	B29	UART_1_RXD	I	+1.8V		UART_1 Receive Data
	GND	A30	B30	GND	PWR			

2.23.8 Low-Speed IO Pins 3 Female (X15)

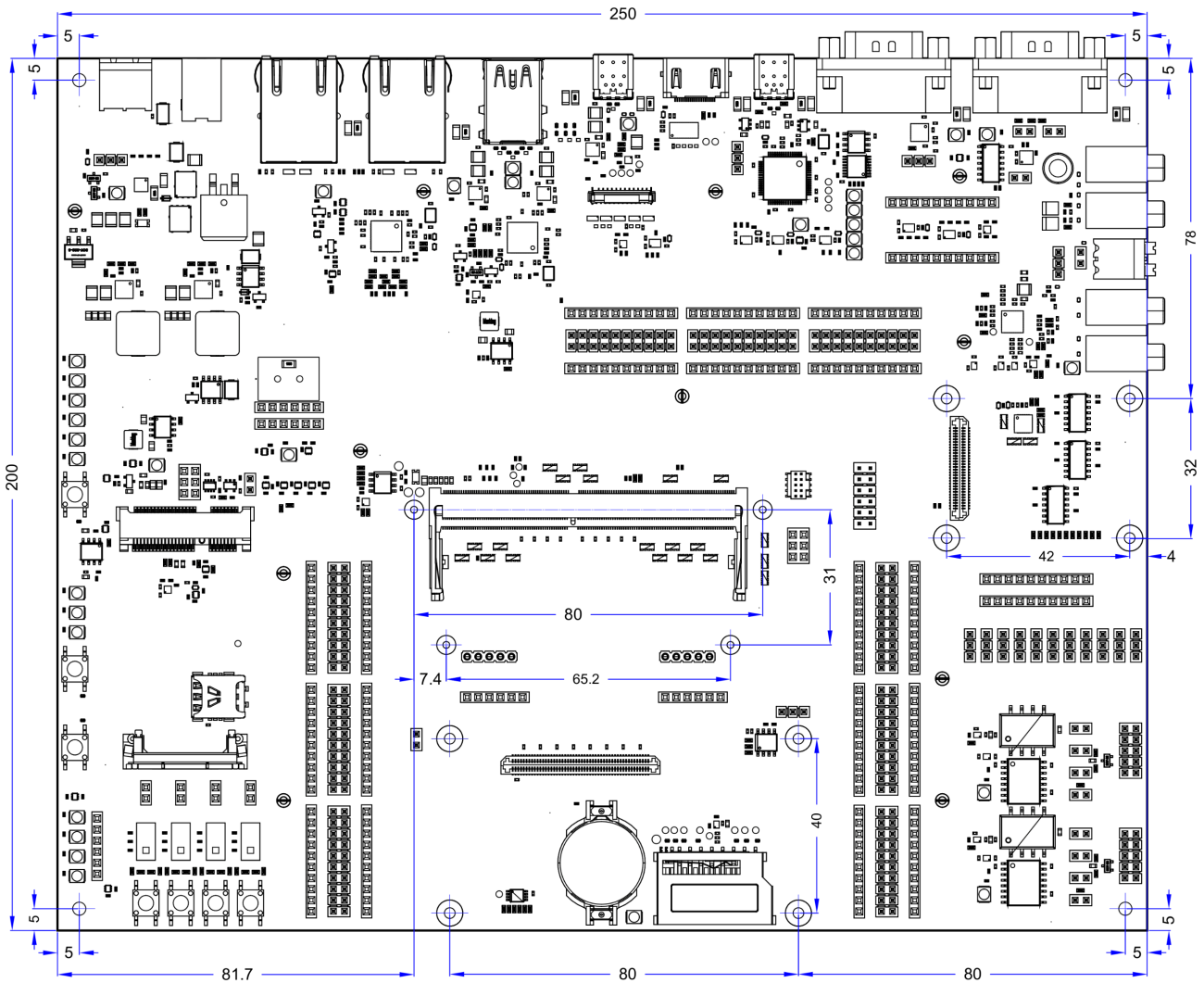
Connector Type: 1×30 Pin Female, 2.54mm Pinout identical to X16 Pins A1 to A30

2.23.9 Function 3 Female (X17)

Connector Type: 1×30 Pin Female, 2.54mm Pinout identical to X16 Pins B1 to B30

3 Mechanical Data

Figure 12: Verdin Development Board dimensions (in millimeters)



4 Design Data

The design data for Toradex Development Board is freely available in the Altium Designer format. The design data includes schematics, layout, and component libraries.

To download the Development Board design data, please use the link below: <http://developer.toradex.com/carrier-board-design>

5 Product Compliance

Up-to-date information about product compliance such as RoHS, CE, UL-94, Conflict Mineral, REACH, etc. can be found on our website at <http://www.toradex.com/support/product-compliance>

6 Device and Documentation Support

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